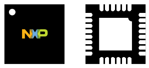
MCX C04x Microcontroller

ARM® Cortex®-M0+ 48MHz 32-bit MCU, 32KB Flash, 2KB SRAM

Rev. 3 — 14 May 2025

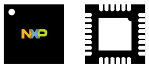
Product data sheet



16-pin QFN (FG)

3 x 3 x 0.65 Pitch 0.5

mm



24-pin QFN (FK)

4 x 4 x 0.65 Pitch 0.5

mm

Features

- Arm® Cortex®-M0+ 48MHz with low power
- 32KB Flash, 2KB SRAM, 8KB Boot ROM
- Run power consumption as low as 50 μA/MHz
- - 40 °C to + 125 °C (Tj) temperature range

Core Processor

- ARM® 32-bit Cortex®-M0+ core up to 48 MHz

Memories

- Up to 32 KB program flash memory
- 2 KB SRAM
- 8 KB ROM with build-in bootloader
- 16 bytes register file

Security

- 80-bit unique identification number per chip

System and clocks

- COP Software watchdog
- SWD debug interface and Micro Trace Buffer
- Bit Manipulation Engine
- 48 MHz high accuracy internal reference clock
- 8/2 MHz low power internal reference clock
- 32 kHz to 40 kHz crystal oscillator
- 1 kHz LPO clock

Communication interfaces for connectivity

- One 8-bit SPI module
- One LPUART module
- One I2C module supporting up to 1 Mbit/s, with double buffer

Analog

- 12-bit SAR ADC with internal voltage reference, up to 818 ksps and 7 channels
- High-speed analog comparator containing a 6-bit DAC and programmable reference input

- 1.2 V voltage reference (Vref)

Timers

- Two 2-channel Timer/PWM modules
- One low-power timer
- Real-time clock

General-purpose input/outputs

- General-purpose input/output up to 22

Power management

- Nine low-power modes to provide power optimization based on application requirements
- Static power consumption as low as 2.2 μA with 7.5 μs wakeup time for full retention and lowest static mode down to 77 nA in deep
- Low-leakage wakeup unit
- Voltage range: 1.71 to 3.6 V
- Flash write voltage range: 1.71 to 3.6 V
- Temperature range : -40 to 125°C(Tj)

Target applications

- Small to medium appliances
- Home security and surveillance
- Smart lighting
- Smart power socket
- DC fan

Table 1. Ordering Information

Part number	Marking	Core speed (MHz)	Flash (KB)	SRAM (KB)	GPIOs	Pin count	Package	Packing
(P)MCXC041VFG(R)	(P)MC1G	48	32	2	14	16	QFN	Tray and Reel
(P)MCXC041VFK(R)	(P)MC041K	48	32	2	22	24	QFN	Tray and Reel

The following figures show the Functional block diagram and Architecture diagram:

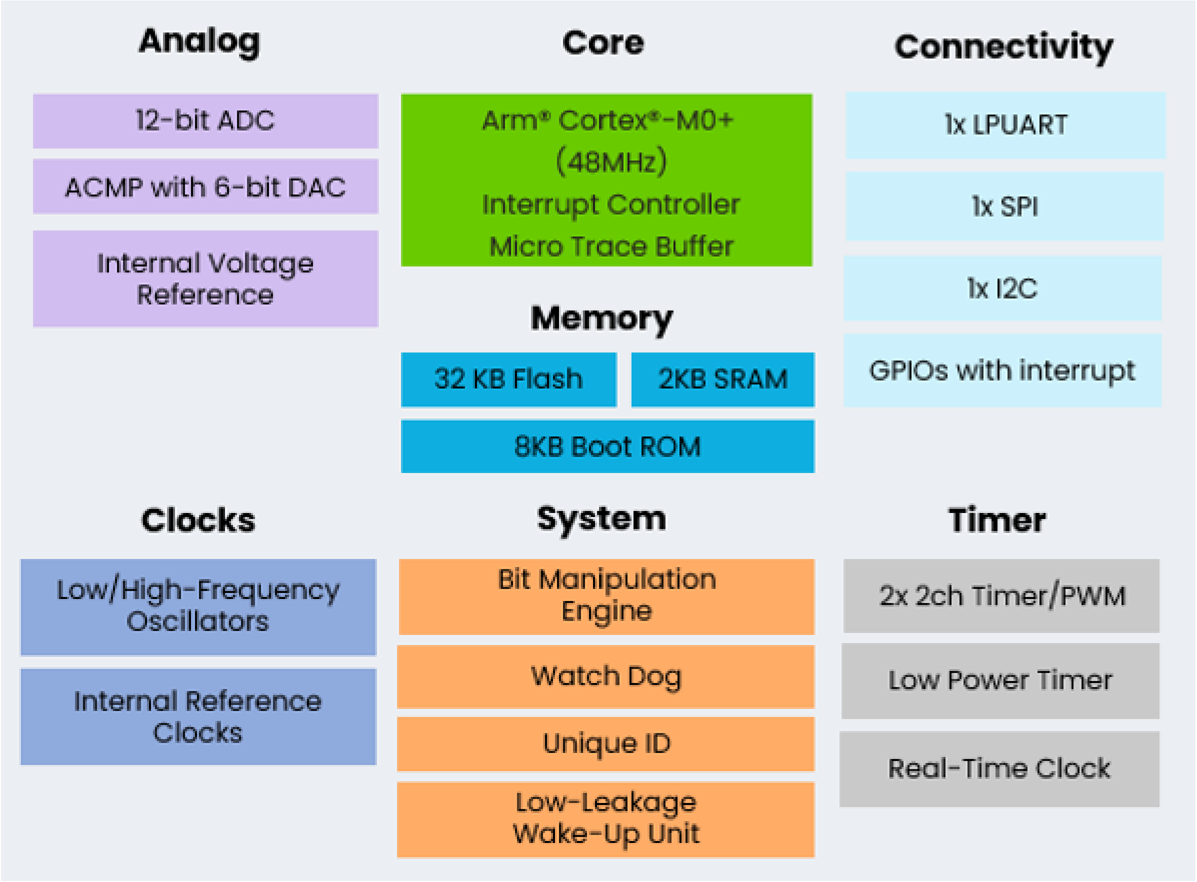


Figure 1. Functional block diagram

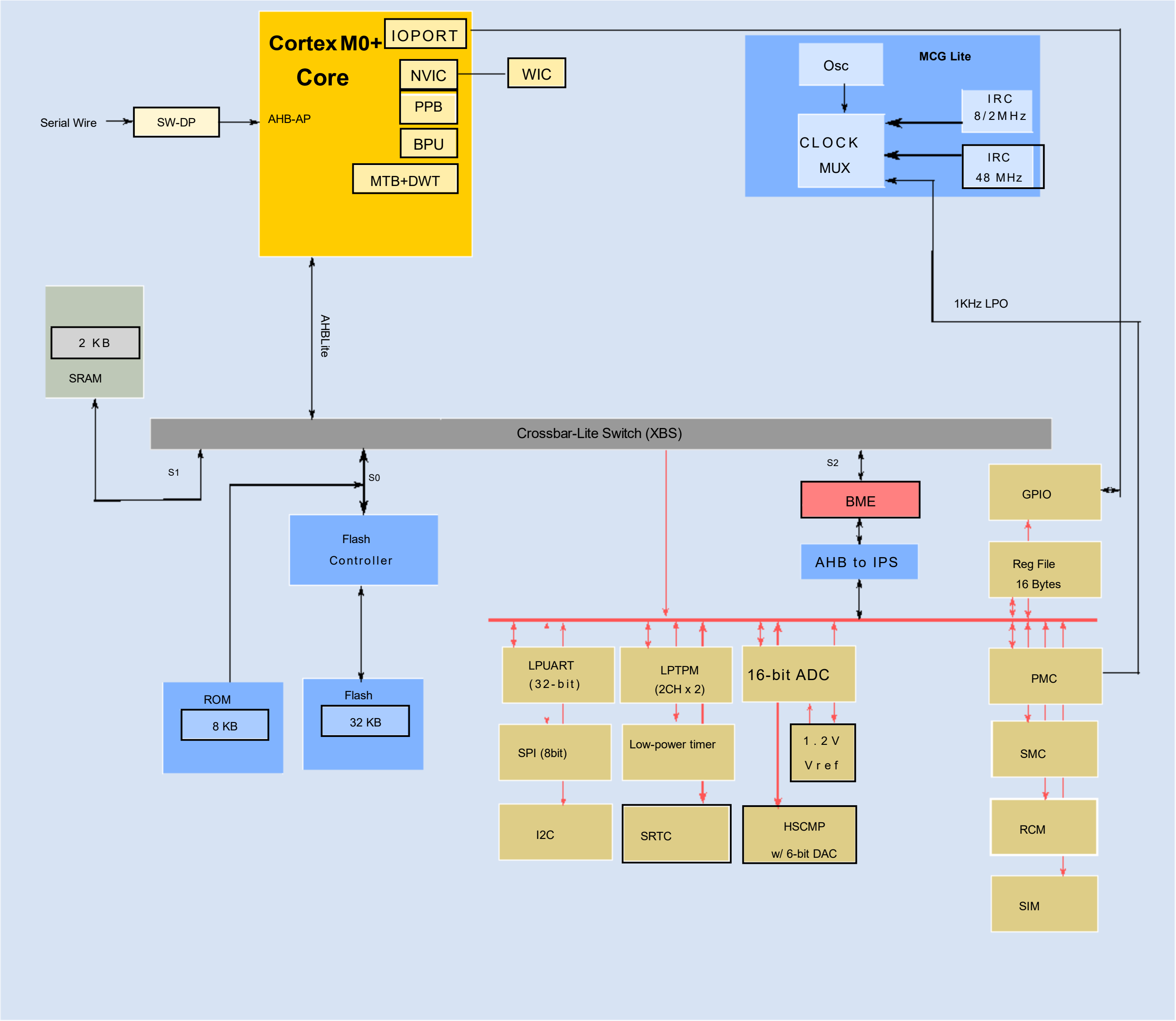


Figure 2. Architecture diagram

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1 Ratings

1.1 Thermal handling ratings

Table 1. Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T_{STG}	Storage temperature	–55	150	°C	1
T_{SDR}	Solder temperature, lead-free	—	260	°C	2

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.2 Moisture handling ratings

Table 2. QFN packages moisture handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
MSL	Moisture sensitivity level	—	3	—	1

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.3 ESD handling ratings

Table 3. ESD handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
V_{HBM}	Electrostatic discharge voltage, human body model	–2000	+2000	V	1
V_{CDM}	Electrostatic discharge voltage, charged-device model	–500	+500	V	2
I_{LAT}	Latch-up current at ambient temperature of 105 °C	–100	+100	mA	3

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.
3. Determined according to JEDEC Standard JESD78, *IC Latch-Up Test*.

1.4 Voltage and current operating ratings

Table 4. Voltage and current operating ratings

Symbol	Description	Min.	Max.	Unit
V_{DD}	Digital supply voltage	–0.3	3.8	V
I_{DD}	Digital supply current	—	120	mA
V_{IO}	IO pin input voltage	–0.3	V_{DD} + 0.3	V
I_D	Instantaneous maximum current single pin limit (applies to all port pins)	–25	25	mA
V_{DDA}	Analog supply voltage	V_{DD} – 0.3	V_{DD} + 0.3	V

2 General

2.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.

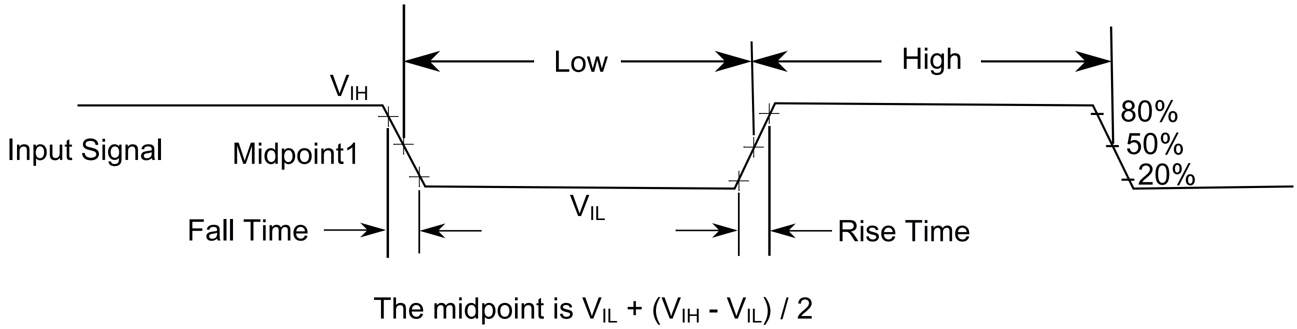


Figure 3. Input signal measurement reference

All digital I/O switching characteristics, unless otherwise specified, assume the output pins have the following characteristics.

- C_L=30 pF loads
- Slew rate disabled
- Normal drive strength

2.2 Nonswitching electrical specifications

2.2.1 Voltage and current operating requirements

Table 5. Voltage and current operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	3.6	V	
V_{DDA}	Analog supply voltage	1.71	3.6	V	—
$V_{DD} – V_{DDA}$	V_{DD}-to-V_{DDA} differential voltage	–0.1	0.1	V	—
$V_{SS} – V_{SSA}$	V_{SS}-to-V_{SSA} differential voltage	–0.1	0.1	V	—
V_{IH}	Input high voltage				—
	• $2.7 V \le V_{DD} \le 3.6 V$	$0.7 \times V_{DD}$	—	V	
	• $1.7 V \le V_{DD} \le 2.7 V$	$0.75 \times V_{DD}$	—	V	
V_{IL}	Input low voltage				—
	• $2.7 V \le V_{DD} \le 3.6 V$	—	$0.35 \times V_{DD}$	V	
	• $1.7 V \le V_{DD} \le 2.7 V$	—	$0.3 \times V_{DD}$	V	
V_{HYS}	Input hysteresis	$0.06 \times V_{DD}$	—	V	—
I_{ICIO}	IO pin negative DC injection current—single pin • $V_{IN} < V_{SS}–0.3V$	–5	—	mA	1
I_{ICcont}	Contiguous pin DC injection current —regional limit, includes sum of negative injection currents of 16 contiguous pins • Negative current injection	–25	—	mA	—
V_{RAM}	V_{DD} voltage required to retain RAM	1.2	—	V	—

1. All I/O pins are internally clamped to V_{SS} through a ESD protection diode. There is no diode connection to V_{DD}. If V_{IN} greater than V_{IO_MIN} (= V_{SS}-0.3 V) is observed, then there is no need to provide current limiting resistors at the pads. If this limit cannot be observed then a current limiting resistor is required. The negative DC injection current limiting resistor is calculated as $R = (V_{IO\_MIN} - V_{IN})/|I_{ICIO}|$.

2.2.2 LVD and POR operating requirements

Table 6. V_{DD} supply LVD and POR operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{POR}	Falling V_{DD} POR detect voltage	0.8	1.1	1.5	V	—
V_{LVDH}	Falling low-voltage detect threshold — high range (LVDV = 01)	2.48	2.56	2.64	V	—
	Low-voltage warning thresholds — high range					1
V_{LVW1H}	• Level 1 falling (LVWV = 00)	2.62	2.70	2.78	V	
V_{LVW2H}	• Level 2 falling (LVWV = 01)	2.72	2.80	2.88	V	

Table continues on the next page...

Table 6. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{LVW3H}	• Level 3 falling (LVWV = 10)	2.82	2.90	2.98	V	
V_{LVW4H}	• Level 4 falling (LVWV = 11)	2.92	3.00	3.08	V	
V_{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	±60	—	mV	—
V_{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	—
	Low-voltage warning thresholds — low range					1
V_{LVW1L}	• Level 1 falling (LVWV = 00)	1.74	1.80	1.86	V	
V_{LVW2L}	• Level 2 falling (LVWV = 01)	1.84	1.90	1.96	V	
V_{LVW3L}	• Level 3 falling (LVWV = 10)	1.94	2.00	2.06	V	
V_{LVW4L}	• Level 4 falling (LVWV = 11)	2.04	2.10	2.16	V	
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	±40	—	mV	—
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	—
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	μs	—

1. Rising thresholds are falling threshold + hysteresis voltage

2.2.3 Voltage and current operating behaviors

Table 7. Voltage and current operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
V_{OH}	Output high voltage — Normal drive pad (except $\overline{\text{RESET}}$)				1, 2
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –5 mA	V_{DD} – 0.5	—	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –2.5 mA	V_{DD} – 0.5	—	V	
V_{OH}	Output high voltage — High drive pad (except $\overline{\text{RESET}}$)				1, 2
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –20 mA	V_{DD} – 0.5	—	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –10 mA	V_{DD} – 0.5	—	V	
I_{OHT}	Output high current total for all ports	—	100	mA	—
V_{OL}	Output low voltage — Normal drive pad				1
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 5 mA	—	0.5	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 2.5 mA	—	0.5	V	
V_{OL}	Output low voltage — High drive pad				1

Table continues on the next page...

Table 7. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Max.	Unit	Notes
	- $2.7\ V \le V_{DD} \le 3.6\ V$, $I_{OL} = 20\ mA$ - $1.71\ V \le V_{DD} \le 2.7\ V$, $I_{OL} = 10\ mA$	— —	0.5 0.5	V V	
I_{OLT}	Output low current total for all ports	—	100	mA	—
I_{IN}	Input leakage current (per pin) for full temperature range	—	1	μA	3
I_{IN}	Input leakage current (per pin) at 25 °C	—	0.025	μA	3
I_{IN}	Input leakage current (total all pins) for full temperature range	—	41	μA	3
I_{OZ}	Hi-Z (off-state) leakage current (per pin)	—	1	μA	—
R_{PU}	Internal pullup resistors	20	50	kΩ	4
R_{PD}	Internal pulldown resistors	20	50	kΩ	5

1. I/O have both high drive and normal drive capability selected by the associated PTx_PCRn[DSE] control bit. All other GPIOs are normal drive only.
2. The reset pin only contains an active pull down device when configured as the RESET signal or as a GPIO. When configured as a GPIO output, it acts as a pseudo open drain output.
3. Measured at $V_{DD} = 3.6$ V
4. Measured at V_{DD} supply voltage = V_{DD} min and Vinput = V_{SS}
5. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR} and VLLSx→RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 48 MHz
- Bus and flash clock = 24 MHz
- HIRC clock mode

VLLSx→RUN recovery uses LIRC clock mode at the default CPU and system frequency of 8 MHz, and a bus and flash clock frequency of 4 MHz.

Table 8. Power mode transition operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Note
t_{POR}	After a POR event, amount of time from the point V_{DD} reaches 1.8 V to execution of the first instruction across the operating temperature range of the chip.	—	—	300	μs	1
	- VLLS0 → RUN	—	152	166	μs	

Table continues on the next page...

Table 8. Power mode transition operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Note
	• VLLS1 → RUN	—	152	166	µs	
	• VLLS3 → RUN	—	93	104	µs	
	• VLPS → RUN	—	7.5	8	µs	
	• STOP → RUN	—	7.5	8	µs	

1. Normal boot (FTFA_FOPT[LPBOOT]=11).

2.2.5 Power consumption operating behaviors

Table 9. MCX C041 QFN packages power consumption operating behaviors

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
I_{DDA}	Analog supply current	—	—	See note	mA	2
I_{DD_RUNCO}	Running CoreMark in flash in compute operation mode—48M HIRC mode, 48 MHz core / 24 MHz flash, V_{DD} = 3.0 V • at 25 °C • at 105 °C	 — —	 5.49 5.62	 5.71 5.84	mA	3
I_{DD_RUNCO}	Running While(1) loop in flash in compute operation mode—48M HIRC mode, 48 MHz core / 24 MHz flash, V_{DD} = 3.0 V • at 25 °C • at 105 °C	 — —	 5.16 5.27	 5.37 5.48	mA	3
I_{DD_RUN}	Run mode current—48M HIRC mode, running CoreMark in Flash all peripheral clock disable 48 MHz core/24 MHz flash, V_{DD} = 3.0 V • at 25 °C • at 105 °C	 — —	 6.03 6.16	 6.27 6.41	mA	3
I_{DD_RUN}	Run mode current—48M HIRC mode, running CoreMark in flash all peripheral clock disable, 24 MHz core/12 MHz flash, V_{DD} = 3.0 V • at 25 °C • at 105 °C	 — —	 3.71 3.81	 3.86 3.96	mA	3
I_{DD_RUN}	Run mode current—48M HIRC mode, running CoreMark in Flash all peripheral clock disable 12 MHz core/6 MHz flash, V_{DD} = 3.0 V	—	2.47	2.57	mA	3

Table continues on the next page...

Table 9. MCX C041 QFN packages power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
	- at 25 °C - at 105 °C	—	2.58	2.68		
I_{DD_RUN}	Run mode current—48M HIRC mode, running CoreMark in Flash all peripheral clock enable 48 MHz core/24 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	6.43 6.56	6.69 6.82	mA	3
I_{DD_RUN}	Run mode current—48M HIRC mode, running While(1) loop in flash all peripheral clock disable, 48 MHz core/24 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	5.71 5.82	5.94 6.05	mA	—
I_{DD_RUN}	Run mode current—48M HIRC mode, running While(1) loop in Flash all peripheral clock disable, 24 MHz core/12 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	3.3 3.4	3.43 3.54	mA	—
I_{DD_RUN}	Run mode current—48M HIRC mode, Running While(1) loop in Flash all peripheral clock disable, 12 MHz core/6 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	2.28 2.38	2.37 2.48	mA	—
I_{DD_RUN}	Run mode current—48M HIRC mode, Running While(1) loop in Flash all peripheral clock enable, 48 MHz core/24 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	6.1 6.22	6.34 6.47	mA	—
I_{DD_RUN}	Run mode current—48M HIRC mode, running While(1) loop in SRAM all peripheral clock disable, 48 MHz core/24 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	3.14 3.27	3.23 3.36	mA	—
I_{DD_RUN}	Run mode current—48M HIRC mode, running While(1) loop in SRAM all peripheral clock enable, 48 MHz core/24 MHz flash, V_{DD} = 3.0 V - at 25 °C - at 105 °C	— —	3.54 3.67	3.63 3.76	mA	—

Table continues on the next page...

Table 9. MCX C041 QFN packages power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
I_{DD_VLPRCO}	Very-low-power run While(1) loop in flash in compute operation mode— 2 MHz LIRC mode, 2 MHz core/0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	500	750	µA	—
I_{DD_VLPRCO}	Very-low-power-run While(1) loop in SRAM in compute operation mode— 8 MHz LIRC mode, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	188	217	µA	—
I_{DD_VLPRCO}	Very-low-power run While(1) loop in SRAM in compute operation mode:—2 MHz LIRC mode, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	82	123	µA	—
I_{DD_VLPR}	Very-low-power run mode current— 2 MHz LIRC mode, While(1) loop in flash all peripheral clock disable, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	503	754	µA	—
I_{DD_VLPR}	Very-low-power run mode current— 2 MHz LIRC mode, While(1) loop in flash all peripheral clock disable, 125 kHz core / 31.25 kHz flash, V_{DD} = 3.0 V • at 25 °C	—	60	90	µA	—
I_{DD_VLPR}	Very-low-power run mode current— 2 MHz LIRC mode, While(1) loop in flash all peripheral clock enable, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	516	774	µA	—
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in SRAM in all peripheral clock disable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	209	350	µA	—
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in SRAM all peripheral clock enable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	229	370	µA	—
I_{DD_VLPR}	Very-low-power run mode current—2 MHz LIRC mode, While(1) loop in SRAM in all peripheral clock disable, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	93	140	µA	—
I_{DD_VLPR}	Very-low-power run mode current—2 MHz LIRC mode, While(1) loop in SRAM all peripheral clock disable, 125 kHz core / 31.25 kHz flash, V_{DD} = 3.0 V • at 25 °C	—	31	81	µA	—
I_{DD_VLPR}	Very-low-power run mode current—2 MHz LIRC mode, While(1) loop in SRAM all					—

Table continues on the next page...

Table 9. MCX C041 QFN packages power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
	peripheral clock enable, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V - at 25 °C	—	103	154	µA	
I_{DD_WAIT}	Wait mode current—core disabled, 48 MHz system/24 MHz bus, flash disabled (flash doze enabled), all peripheral clocks disabled, MCG_Lite under HIRC mode, V_{DD} = 3.0 V	—	1.4	1.94	mA	—
I_{DD_WAIT}	Wait mode current—core disabled, 24 MHz system/12 MHz bus, flash disabled (flash doze enabled), all peripheral clocks disabled, MCG_Lite under HIRC mode, V_{DD} = 3.0 V	—	1.02	1.24	mA	—
I_{DD_VLPW}	Very-low-power wait mode current, core disabled, 4 MHz system/ 1 MHz bus and flash, all peripheral clocks disabled, V_{DD} = 3.0 V	—	121	181	µA	—
I_{DD_VLPW}	Very-low-power wait mode current, core disabled, 2 MHz system/ 0.5 MHz bus and flash, all peripheral clocks disabled, V_{DD} = 3.0 V	—	59	97	µA	—
I_{DD_VLPW}	Very-low-power wait mode current, core disabled, 125 kHz system/ 31.25 kHz bus and flash, all peripheral clocks disabled, V_{DD} = 3.0 V	—	28	42	µA	—
I_{DD_PSTOP2}	Partial Stop 2, core and system clock disabled, 12 MHz bus and flash, V_{DD} = 3.0 V	—	1.53	2.03	mA	—
I_{DD_PSTOP2}	Partial Stop 2, core and system clock disabled, flash doze enabled, 12 MHz bus, V_{DD} = 3.0 V	—	0.881	1.18	mA	—
I_{DD_STOP}	Stop mode current at 3.0 V - at 25 °C and below - at 50 °C - at 85 °C - at 105 °C	— — — —	158 164 187 219	175.7 179.48 199.54 236.43	µA	—
I_{DD_VLPS}	Very-low-power stop mode current at 3.0 V - at 25 °C and below - at 50 °C - at 85 °C - at 105 °C	— — — —	2.2 3.9 13.9 28.4	2.71 6.63 18.25 36.59	µA	—
I_{DD_VLPS}	Very-low-power stop mode current at 1.8 V - at 25 °C and below - at 50 °C	— — —	2.2 3.8 13.2	2.674 6.44 17.37	µA	—

Table continues on the next page...

Table 9. MCX C041 QFN packages power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
	- at 85 °C - at 105 °C	—	27.8	35.54		
I_{DD_VLLS3}	Very-low-leakage stop mode 3 current, all peripheral disable, at 3.0 V - at 25 °C and below - at 50 °C - at 85 °C - at 105 °C	— — — —	1.08 1.4 3.45 7.02	1.17 1.52 3.96 8.19	μA	—
I_{DD_VLLS3}	Very-low-leakage stop mode 3 current with RTC current, at 3.0 V - at 25 °C and below - at 50 °C - at 85 °C - at 105 °C	— — — —	1.47 1.82 3.93 7.6	1.56 1.94 4.44 8.77	μA	—
I_{DD_VLLS3}	Very-low-leakage stop mode 3 current with RTC current, at 1.8 V - at 25 °C and below - at 50 °C - at 85 °C - at 105 °C	— — — —	1.33 1.65 3.56 6.92	1.42 1.77 4.07 8.09	μA	—
I_{DD_VLLS1}	Very-low-leakage stop mode 1 current all peripheral disabled at 3.0 V - at 25 °C and below - at 50°C - at 85°C - at 105 °C	— — — —	566 788 2270 4980	690 839 2600 5820	nA	—
I_{DD_VLLS1}	Very-low-leakage stop mode 1 current RTC enabled at 3.0 V - at 25 °C and below - at 50°C - at 85°C - at 105 °C	— — — —	969 1200 2740 5610	1059 1251 3070 6450	nA	—
I_{DD_VLLS1}	Very-low-leakage stop mode 1 current RTC enabled at 1.8 V - at 25 °C and below - at 50°C - at 85°C - at 105 °C	— — — —	826 1040 2400 4910	916 1091 2730 5750	nA	—

Table continues on the next page...

Table 9. MCX C041 QFN packages power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.[1]	Unit	Notes
I_{DD_VLLS0}	Very-low-leakage stop mode 0 current all peripheral disabled (SMC_STOPCTRL[PORPO] = 0) at 3.0 V • at 25 °C and below • at 50 °C • at 85 °C • at 105 °C	 — — — —	 265 467 1920 4540	 373 512.9 2256 5395	nA	—
I_{DD_VLLS0}	Very-low-leakage stop mode 0 current all peripheral disabled (SMC_STOPCTRL[PORPO] = 1) at 3 V • at 25 °C and below • at 50 °C • at 85 °C • at 105 °C	 — — — —	 77 255 1640 4080	 350 465.70 1994 4956	nA	4

1. The maximum values represent characterized results equivalent to the mean plus three times the standard deviation (mean + 3 sigma).
2. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
3. MCG_Lite configured for HIRC mode. CoreMark benchmark compiled using IAR with optimization level high, optimized for balanced.
4. No brownout

Table 10. Low power mode peripheral adders — typical value

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105[1]	
$I_{LIRC8MHz}$	8 MHz internal reference clock (LIRC) adder. Measured by entering STOP or VLPS mode with 8 MHz LIRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	68	68	68	68	68	68	µA
$I_{LIRC2MHz}$	2 MHz internal reference clock (LIRC) adder. Measured by entering STOP mode with the 2 MHz LIRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	27	27	27	27	27	27	µA
$I_{EREFSTEN32KHz}$	External 32 kHz crystal clock adder by means of the OSC0_CR[EREFSTEN and EREFSTEN] bits. Measured by entering all modes with the crystal enabled. • VLLS1 • VLLS3 • VLPS • STOP	 340 340 340 340	 410 410 420 420	 460 460 480 480	 470 490 570 570	 480 530 610 610	 600 600 850 850	nA

Table continues on the next page...

Table 10. Low power mode peripheral adders — typical value (continued)

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105[1]	
I_{LPTMR}	LPTMR peripheral adder measured by placing the device in VLLS1 mode with LPTMR enabled using LPO.	30	30	30	85	100	200	nA
I_{CMP}	CMP peripheral adder measured by placing the device in VLLS1 mode with CMP enabled using the 6-bit DAC and a single external input for compare. Includes 6-bit DAC power consumption.	15	15	15	15	15	15	µA
I_{RTC}	RTC peripheral adder measured by placing the device in VLLS1 mode with external 32 kHz crystal enabled by means of the RTC_CR[OSCE] bit and the RTC ALARM set for 1 minute. Includes ERCLK32K (32 kHz external crystal) power consumption.	340	440	440	480	520	620	nA
I_{UART}	UART peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source waiting for RX data at 115200 baud rate. Includes selected clock source power consumption. • LIRC8M (8 MHz internal reference clock) • LIRC2M (2 MHz internal reference clock)	85 28	85 28	85 28	85 28	85 28	85 28	µA
I_{TPM}	TPM peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source configured for output compare generating 100 Hz clock signal. No load is placed on the I/O generating the clock signal. Includes selected clock source and I/O switching currents. • LIRC8M (8 MHz internal reference clock) • LIRC2M (2 MHz internal reference clock)	93 35	93 35	93 35	93 35	93 35	93 35	µA
I_{BG}	Bandgap adder when BGEN bit is set and device is placed in VLPx or VLLSx mode.	45	45	45	45	45	45	µA
I_{ADC}	ADC peripheral adder combining the measured values at V_{DD} and V_{DDA} by placing the device in STOP or VLPS mode. ADC is configured for low power mode using the internal clock and continuous conversions.	340	340	340	340	340	340	µA

1. For QFN packages only.

2.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG-Lite in HIRC for run mode, and LIRC for VLPR mode
- No GPIOs toggled
- Code execution from flash
- For the ALLOFF curve, all peripheral clocks are disabled except FTFA

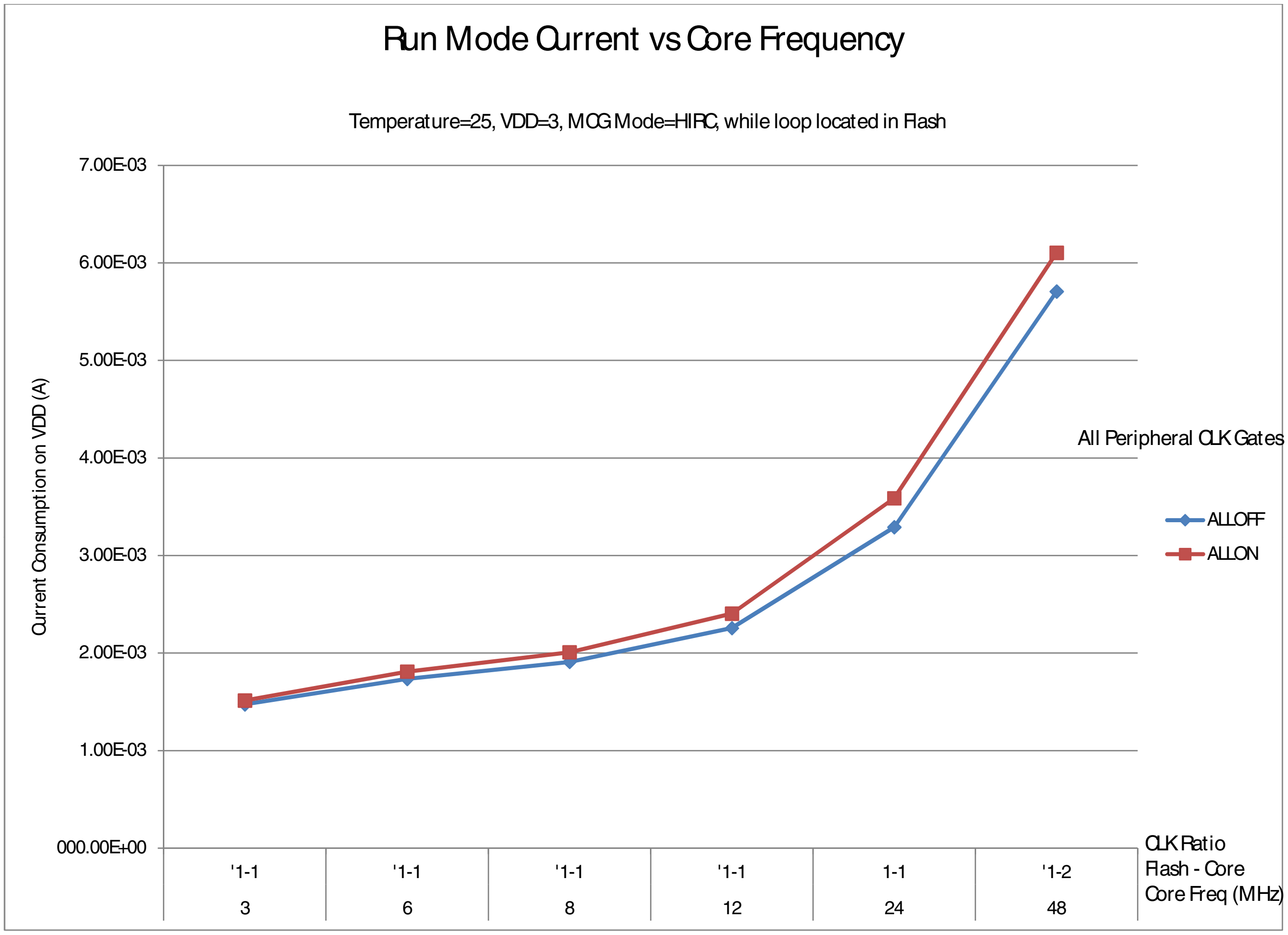


Figure 4. Run mode supply current vs. core frequency (loop located in flash)

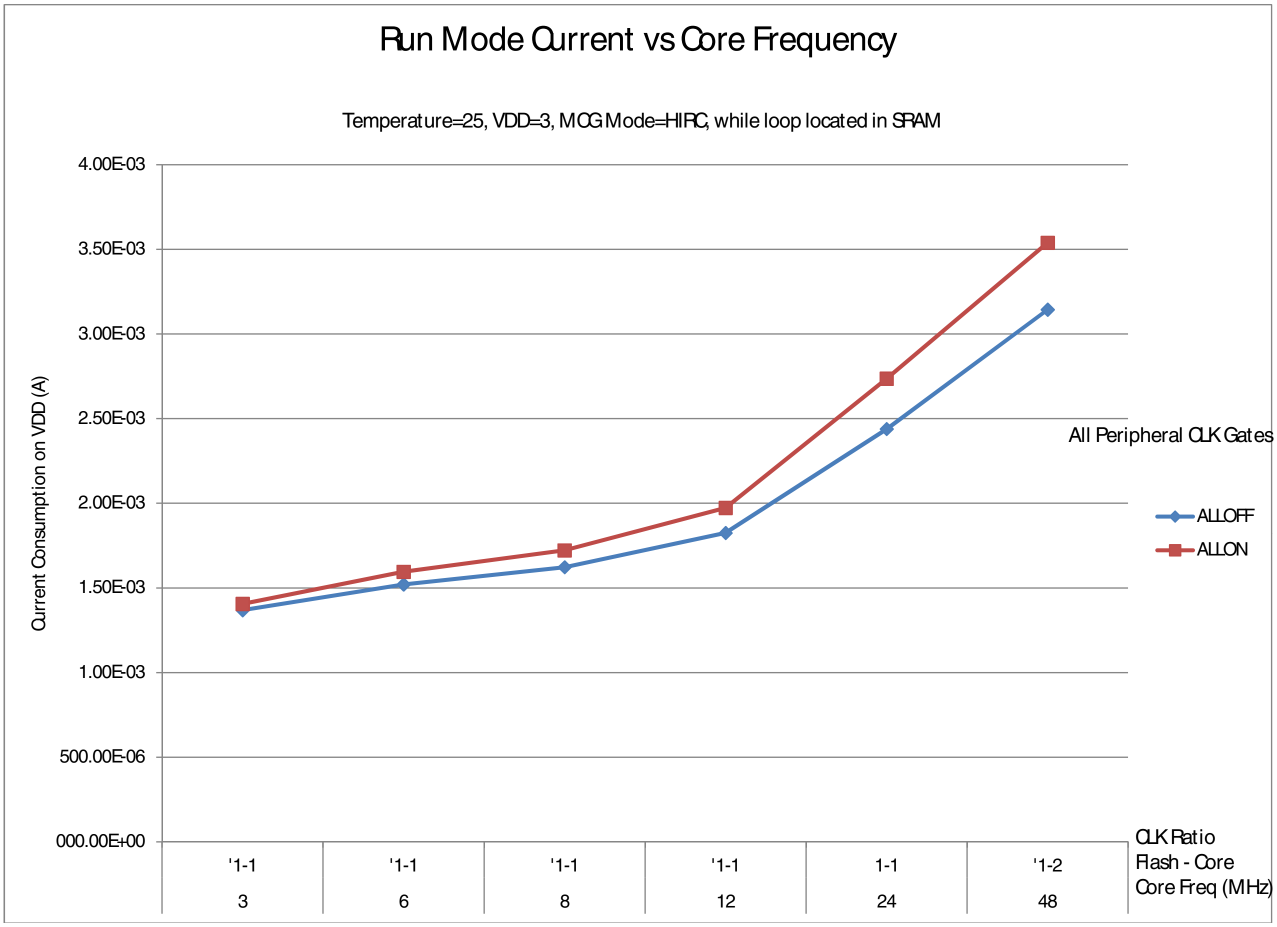


Figure 5. Run mode supply current vs. core frequency (loop located in SRAM)

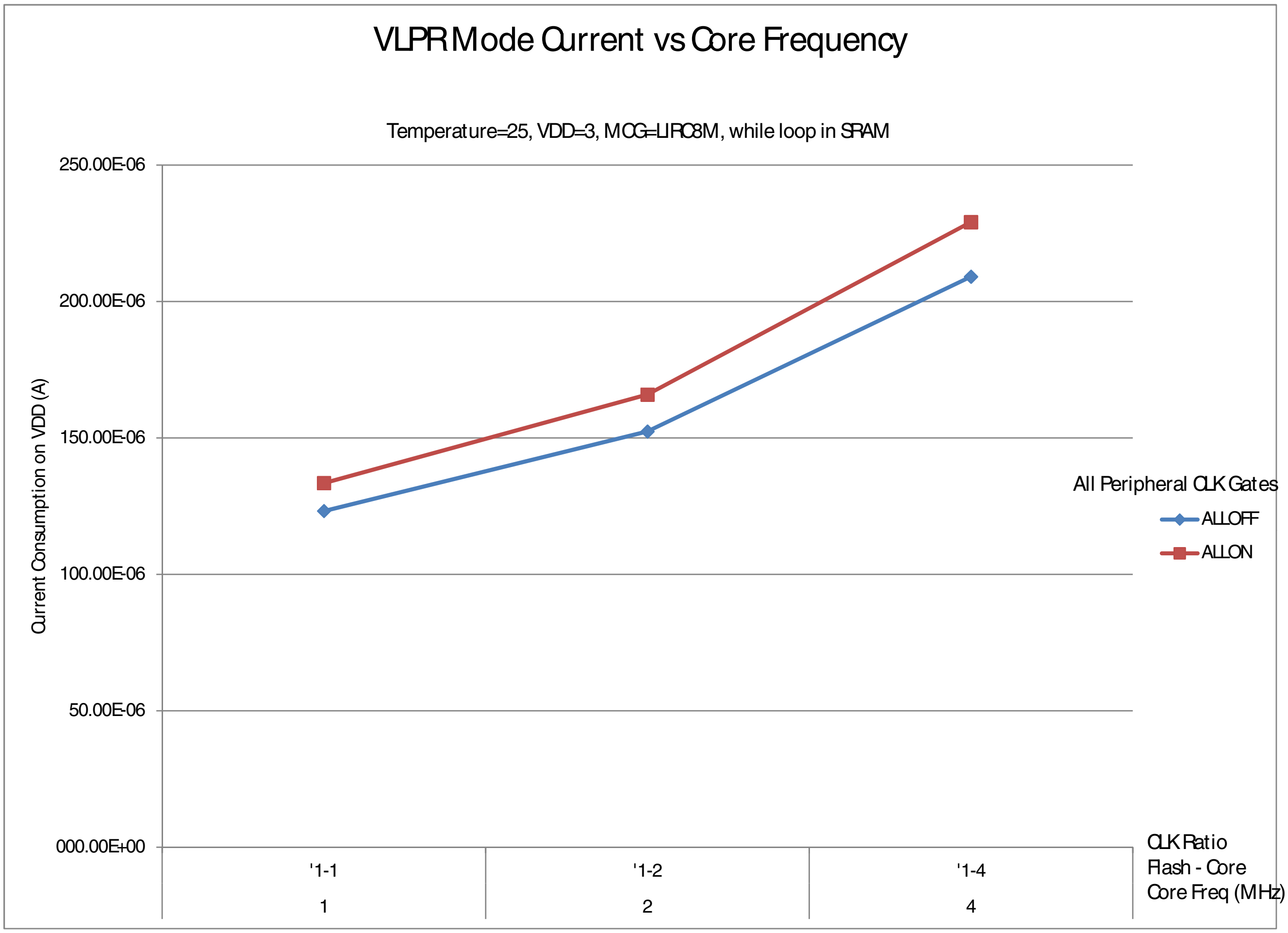


Figure 6. VLPR mode current vs. core frequency (loop in SRAM)

2.2.6 EMC radiated emissions operating behaviors

Table 11. EMC radiated emissions operating behaviors for 24-pin QFN package

Symbol	Description	Frequency band (MHz)	Typ.	Unit	Notes
V_{RE1}	Radiated emissions voltage, band 1	0.15–50	5	dBμV	1, 2
V_{RE2}	Radiated emissions voltage, band 2	50–150	7	dBμV	
V_{RE3}	Radiated emissions voltage, band 3	150–500	5	dBμV	
V_{RE4}	Radiated emissions voltage, band 4	500–1000	5	dBμV	
V_{RE_IEC}	IEC/SAE level	0.15–1000	N	—	2, 3

1. Determined according to IEC 61967-2 (and SAE J1752/3) radiated radio frequency (RF) emissions measurement standard. Typical Configuration: Appendix B: DUT Software Configuration—2. Typical Configuration.
2. V_{DD} = 3.3 V, T_A = 25 °C, f_{irc48m} = 48 MHz, f_{SYS} = 48 MHz, f_{BUS} = 24 MHz
3. IEC/SAE Level Maximums: N≤12 dBμV, M≤18 dBμV, L≤24 dBμV, K≤30 dBμV, I ≤ 36 dBμV, H ≤ 42 dBμV, G≤48 dBμV.

2.2.7 EMC Radiated Emissions Web Search Procedure boilerplate

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to www.nxp.com.
2. Perform a keyword search for "EMC design"

2.2.8 Capacitance attributes

Table 12. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C_{IN}	Input capacitance	—	7	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 13. Device clock specifications

Symbol	Description	Min.	Max.	Unit
Normal run mode				
f_{SYS}	System and core clock	—	48	MHz
f_{BUS}	Bus clock	—	24	MHz
f_{FLASH}	Flash clock	—	24	MHz
f_{LPTMR}	LPTMR clock	—	24	MHz
VLPR and VLPS modes[1]				
f_{SYS}	System and core clock	—	4	MHz
f_{BUS}	Bus clock	—	1	MHz
f_{FLASH}	Flash clock	—	1	MHz
f_{LPTMR}	LPTMR clock[2]	—	24	MHz
f_{ERCLK}	External reference clock	—	16	MHz
f_{LPTMR_ERCLK}	LPTMR external reference clock	—	16	MHz
f_{TPM}	TPM asynchronous clock	—	8	MHz
f_{UART0}	UART0 asynchronous clock	—	8	MHz

1. The frequency limitations in VLPR and VLPS modes here override any frequency specification listed in the timing specification for any other module. These same frequency limits apply to VLPS, whether VLPS was entered from RUN or from VLPR.
2. The LPTMR can be clocked at this speed in VLPR or VLPS only when the source is an external pin.

2.3.2 General switching specifications

These general-purpose specifications apply to all signals configured for GPIO and UART signals.

Table 14. General switching specifications

Description	Min.	Max.	Unit	Notes
GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1
External RESET and NMI pin interrupt pulse width — Asynchronous path	100	—	ns	2
GPIO pin interrupt pulse width — Asynchronous path	16	—	ns	2
Port rise and fall time	—	36	ns	3

1. The greater synchronous and asynchronous timing must be met.
2. This is the shortest pulse that is guaranteed to be recognized.
3. 75 pF load

2.4 Thermal specifications

2.4.1 Thermal operating requirements

Table 15. Thermal operating requirements

Symbol	Description	Min.	Max.	Unit	Note
T_J	Die junction temperature	–	125	°C	
T_A	Ambient temperature	-40	125	°C	1, 2

1. Maximum T_A can be exceeded only if the user ensures that T_J does not exceed the maximum. The simplest method to determine T_J is: $T_J = T_A + R_{\theta JA} \times$ chip power dissipation.
2. The device operating specification is not guaranteed beyond 125C Tj

2.4.2 Thermal attributes

Table 16. Thermal attributes

Board type	Symbol	Description	16 QFN	20 WLCSP	24 QFN	Unit	Notes
Single-layer (1S)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	64.2	69.8	60.7	°C/W	1,2
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	53.3	57.5	48.5	°C/W	1,2,3
Single-layer (1S)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	55.4	62.03	51.0	°C/W	1,3
Four-layer (2s2p)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	48.9	54.3	43.6	°C/W	1,3
—	$R_{\theta JB}$	Thermal resistance, junction to board	33.5	51.64	30.4	°C/W	4
—	$R_{\theta JC}$	Thermal resistance, junction to case	20.9	0.73	9.8	°C/W	5
—	Ψ_{JT}	Thermal characterization parameter, junction to package top outside center (natural convection)	0.2	0.2	0.2	°C/W	6
—	Ψ_{JB}	Thermal characterization parameter, junction to package bottom outside center (natural convection)	22.4	–	21.8	°C/W	7

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Per SEMI G38-87 and JEDEC JESD51-2 with the single layer board horizontal.
3. Per JEDEC JESD51-6 with the board horizontal.
4. Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.
7. Thermal characterization parameter indicating the temperature difference between package bottom center and the junction temperature per JEDEC JESD51-12. When Greek letters are not available, the thermal characterization parameter is written as Psi-JB.

3 Peripheral operating requirements and behaviors

3.1 Core modules

3.1.1 SWD electricals

Table 17. SWD full voltage range electricals

Symbol	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
J1	SWD_CLK frequency of operation • Serial wire debug	0	25	MHz
J2	SWD_CLK cycle period	1/J1	—	ns
J3	SWD_CLK clock pulse width • Serial wire debug	20	—	ns
J4	SWD_CLK rise and fall times	—	3	ns
J9	SWD_DIO input data setup time to SWD_CLK rise	10	—	ns
J10	SWD_DIO input data hold time after SWD_CLK rise	0	—	ns
J11	SWD_CLK high to SWD_DIO data valid	—	32	ns
J12	SWD_CLK high to SWD_DIO high-Z	5	—	ns

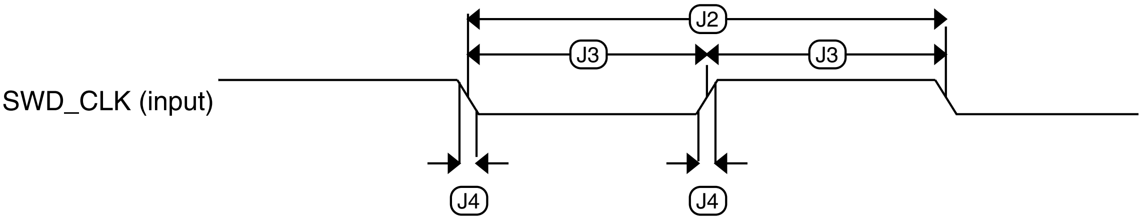


Figure 7. Serial wire clock input timing

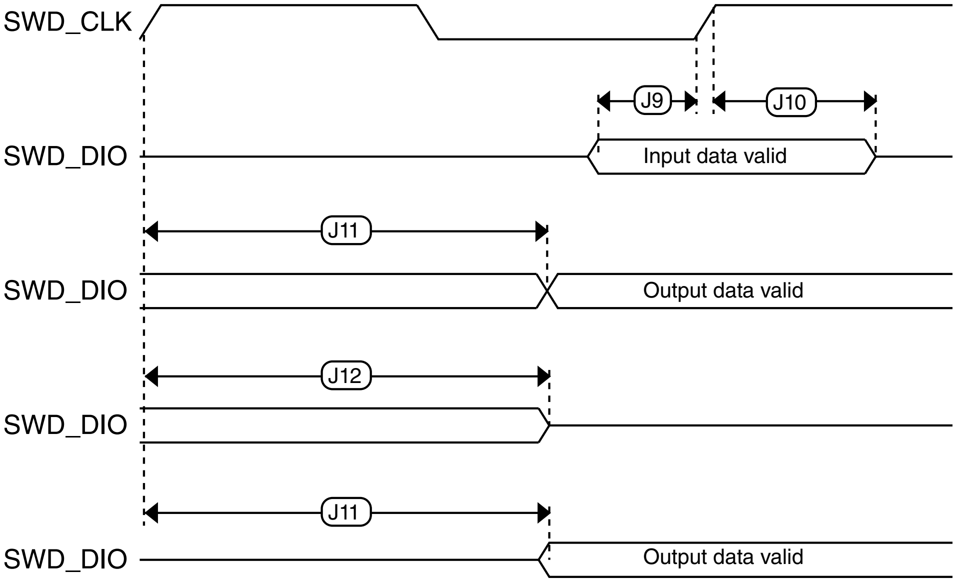


Figure 8. Serial wire data timing

3.2 System modules

There are no specifications necessary for the device's system modules.

3.3 Clock modules

3.3.1 MCG-Lite specifications

Table 18. HIRC48M specification

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	—	3.6	V	—
I_{DD48M}	Supply current	—	400	500	µA	—
f_{irc48m}	Internal reference frequency	—	48	—	MHz	—
$\Delta f_{irc48m\_ol\_lv}$	total deviation of IRC48M frequency at low voltage (VDD=1.71V-1.89V) over temperature	—	± 0.5	TBD±1.5	$\%f_{irc48m}$	—

Table continues on the next page...

Table 18. HIRC48M specification (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$\Delta f_{irc48m\_ol\_hv}$	total deviation of IRC48M frequency at high voltage (VDD=1.89V-3.6V) over temperature	—	± 0.5	TBD±1.0	$\%f_{irc48m}$	—
J_{cyc_irc48m}	Period Jitter (RMS)	—	35	150	ps	—
$t_{irc48mst}$	Startup time	—	2	3	μs	1

1. IRC48M startup time is defined as the time between clock enablement and clock availability for system use. Enable the clock by setting MCG_MC[HIRCEN] = 1. See reference manual for details.

Table 19. LIRC8M/2M specification

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.08	—	1.47	V	—
T	Temperature range	-40	—	125	°C	—
I_{DD_2M}	Supply current in 2 MHz mode	—	14	17	μA	—
I_{DD_8M}	Supply current in 8 MHz mode	—	30	35	μA	—
f_{IRC_2M}	Output frequency	—	2	—	MHz	—
f_{IRC_8M}	Output frequency	—	8	—	MHz	—
$f_{IRC\_UT\_2M}$	Output frequency range (untrimmed)	—	—	±30	$\%f_{IRC}$	—
$f_{IRC\_UT\_8M}$	Output frequency range (untrimmed)	—	—	±30	$\%f_{IRC}$	—
$f_{IRC\_T\_2M}$	Output frequency range (trimmed)	—	—	±3	$\%f_{IRC}$	$V_{DD}\geq 1.89$ V
$f_{IRC\_T\_8M}$	Output frequency range (trimmed)	—	—	±3	$\%f_{IRC}$	$V_{DD}\geq 1.89$ V
T_{su_2M}	Startup time	—	—	12.5	μs	—
T_{su_8M}	Startup time	—	—	12.5	μs	—

3.3.2 Oscillator electrical specifications

3.3.2.1 Oscillator DC electrical specifications

Table 20. Oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	—	3.6	V	
I_{DDOSC}	Supply current — low-power mode • 32 kHz	—	500	—	nA	1
C_x	EXTAL load capacitance	—	—	—		2, 3
C_y	XTAL load capacitance	—	—	—		2, 3

Table continues on the next page...

Table 20. Oscillator DC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
R_F	Feedback resistor — low-frequency, low-power mode	—	—	—	MΩ	2, 4
R_S	Series resistor — low-frequency, low-power mode	—	—	—	kΩ	
V_{pp}[5]	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode	—	0.6	—	V	

1. V_{DD}=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x,C_y can be provided by using either the integrated capacitors or by using external components.
4. When low power mode is selected, R_F is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other devices.

3.3.2.2 Oscillator frequency specifications

Table 21. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low frequency mode	32	—	40	kHz	
t_{dc_extal}	Input clock duty cycle (external clock mode)	40	50	60	%	
t_{cst}	Crystal startup time — 32 kHz low-frequency, low-power mode	—	7501000	—	ms	1, 2

1. Proper PC board layout procedures must be followed to achieve specifications.
2. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

3.4 Memories and memory interfaces

3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 22. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvpgm4}	Longword Program high-voltage time	—	7.5	18	μs	
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversall}$	Erase All high-voltage time	—	52	452	ms	1

1. Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 23. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1sec1k}$	Read 1s Section execution time (flash sector)	—	—	60	μs	1
t_{pgmchk}	Program Check execution time	—	—	45	μs	1
t_{rdrsrc}	Read Resource execution time	—	—	30	μs	1
t_{pgm4}	Program Longword execution time	—	65	145	μs	
t_{ersscr}	Erase Flash Sector execution time	—	14	114	ms	2
t_{rd1all}	Read 1s All Blocks execution time	—	—	0.5	ms	
t_{rdonce}	Read Once execution time	—	—	25	μs	1
$t_{pgmonce}$	Program Once execution time	—	65	—	μs	
t_{ersall}	Erase All Blocks execution time	—	61	500	ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	μs	1

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

3.4.1.3 Flash high voltage current behaviors

Table 24. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I_{DD_PGM}	Average current adder during high voltage flash programming operation	—	2.5	6.0	mA
I_{DD_ERS}	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

3.4.1.4 Reliability specifications

Table 25. NVM reliability specifications

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
Program Flash						

Table continues on the next page...

Table 25. NVM reliability specifications (continued)

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
$t_{nvmretp10k}$	Data retention after up to 10 K cycles	5	50	—	years	
$t_{nvmretp1k}$	Data retention after up to 1 K cycles	20	100	—	years	
$n_{nvmcycp}$	Cycling endurance	10 K	50 K	—	cycles	2

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25 °C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at -40 °C $\leq T_j \leq$ 125 °C.

3.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

3.6 Analog

3.6.1 ADC electrical specifications

All ADC channels meet the 12-bit single-ended accuracy specifications.

3.6.1.1 12-bit ADC operating conditions

Table 26. 12-bit ADC operating conditions

Symbol	Description	Conditions	Min.	Typ.[1]	Max.	Unit	Notes
V_{DDA}	Supply voltage	Absolute	1.71	—	3.6	V	
ΔV_{DDA}	Supply voltage	Delta to V_{DD} ($V_{DD} - V_{DDA}$)	-100	0	+100	mV	2
ΔV_{SSA}	Ground voltage	Delta to V_{SS} ($V_{SS} - V_{SSA}$)	-100	0	+100	mV	2
V_{REFH}	ADC reference voltage high		1.13	V_{DDA}	V_{DDA}	V	3
V_{REFL}	ADC reference voltage low		V_{SSA}	V_{SSA}	V_{SSA}	V	3
V_{ADIN}	Input voltage		V_{REFL}	—	V_{REFH}	V	
C_{ADIN}	Input capacitance	• 8-bit / 10-bit / 12-bit modes	—	4	5	pF	
R_{ADIN}	Input series resistance		—	2	5	kΩ	

Table continues on the next page...

Table 26. 12-bit ADC operating conditions (continued)

Symbol	Description	Conditions	Min.	Typ.[1]	Max.	Unit	Notes
R_{AS}	Analog source resistance (external)	12-bit modes f_{ADCK} < 4 MHz	—	—	5	kΩ	4
f_{ADCK}	ADC conversion clock frequency	≤ 12-bit mode	1.0	—	18.0	MHz	5
C_{rate}	ADC conversion rate	≤ 12-bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time	20.000	—	818.330	Ksps	6

1. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 1.0 MHz, unless otherwise stated. Typical values are for reference only, and are not tested in production.
2. DC potential difference.
3. For packages without dedicated VREFH and VREFL pins, V_{REFH} is internally tied to V_{DDA}, and V_{REFL} is internally tied to V_{SSA}.
4. This resistance is external to MCU. To achieve the best results, the analog source resistance must be kept as low as possible. The results in this data sheet were derived from a system that had < 8 Ω analog source resistance. The R_{AS}/C_{AS} time constant should be kept to < 1 ns.
5. To use the maximum ADC conversion clock frequency, CFG2[ADHSC] must be set and CFG1[ADLPC] must be clear.
6. For guidelines and examples of conversion rate calculation, download the ADC calculator tool.

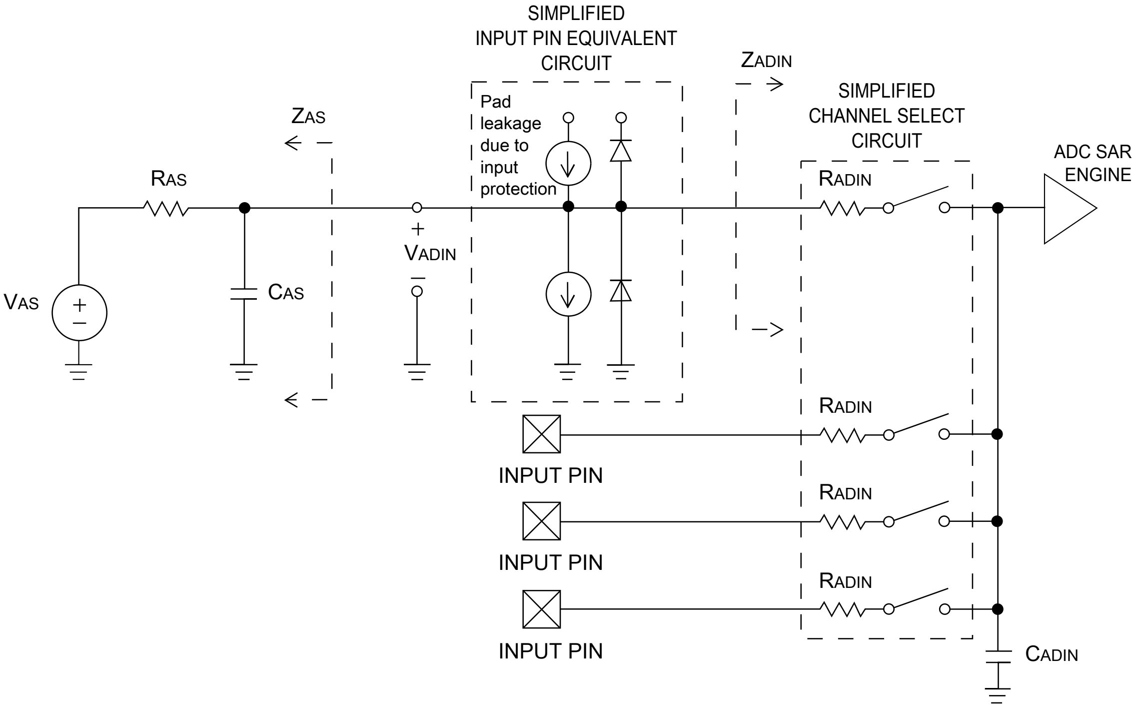


Figure 9. ADC input impedance equivalency diagram

3.6.1.2 12-bit ADC electrical characteristics

Table 27. 12-bit ADC characteristics (V_{REFH} = V_{DDA}, V_{REFL} = V_{SSA})

Symbol	Description	Conditions[1].	Min.	Typ.[2]	Max.	Unit	Notes
I_{DDA_ADC}	Supply current		0.215	—	1.7	mA	3
f_{ADACK}	ADC asynchronous clock source	• ADLPC = 1, ADHSC = 0 • ADLPC = 1, ADHSC = 1 • ADLPC = 0, ADHSC = 0 • ADLPC = 0, ADHSC = 1	1.2 2.4 3.0 4.4	2.4 4.0 5.2 6.2	3.9 6.1 7.3 9.5	MHz MHz MHz MHz	t_{ADACK} = $1/f_{ADACK}$
	Sample Time	See Reference Manual chapter for sample times					
TUE	Total unadjusted error	• 12-bit modes • <12-bit modes	— —	±6 ±3	— ±6	LSB[4]	5
DNL	Differential non-linearity	• 12-bit modes • <12-bit modes	— —	±0.9 ±0.4	–1.1 to +1.9 –0.3 to 0.5	LSB[4]	5
INL	Integral non-linearity	• 12-bit modes • <12-bit modes	— —	±1.5 ±0.5	–2.7 to +1.9 –0.7 to +0.5	LSB[4]	5
E_{FS}	Full-scale error	• 12-bit modes • <12-bit modes	— —	5 2	— 3	LSB[4]	V_{ADIN} = V_{DDA}[5]
E_Q	Quantization error	• 12-bit modes	—	—	±0.5	LSB[4]	
E_{IL}	Input leakage error		$I_{In} \times R_{AS}$			mV	I_{In} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	6
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	6

1. All accuracy numbers assume the ADC is calibrated with V_{REFH} = V_{DDA}
2. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = (V_{REFH} - V_{REFL})/2^N

5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. ADC conversion clock < 3 MHz

Table 28. 12-bit ADC characteristics ($V_{REFH} = V_{REFO}$, $V_{REFL} = V_{SSA}$)

Symbol	Description	Conditions[1].	Min.	Typ.[2]	Max.	Unit	Notes
I_{DDA_ADC}	Supply current		0.215	—	1.7	mA	3
f_{ADACK}	ADC asynchronous clock source	• ADLPC = 1, ADHSC = 0	1.2	2.4	3.9	MHz	$t_{ADACK} = 1/f_{ADACK}$
		• ADLPC = 1, ADHSC = 1	2.4	4.0	6.1	MHz	
		• ADLPC = 0, ADHSC = 0	3.0	5.2	7.3	MHz	
		• ADLPC = 0, ADHSC = 1	4.4	6.2	9.5	MHz	
	Sample Time	See Reference Manual chapter for sample times					
TUE	Total unadjusted error	• 12-bit modes	—	±4	±6.8	LSB[4]	5
		• <12-bit modes	—	±1.4	±2.1		
DNL	Differential non-linearity	• 12-bit modes	—	±0.7	–1.1 to +1.9	LSB[4]	5
		• <12-bit modes	—	±0.2	–0.3 to 0.5		
INL	Integral non-linearity	• 12-bit modes	—	±1.0	–2.7 to +1.9	LSB[4]	5
		• <12-bit modes	—	±0.5	–0.7 to +0.5		
E_{FS}	Full-scale error	• 12-bit modes	—	–4	–5.4	LSB[4]	$V_{ADIN} = V_{DDA}$[5]
		• <12-bit modes	—	–1.4	–1.8		
E_Q	Quantization error	• 12-bit modes	—	—	±0.5	LSB[4]	
E_{IL}	Input leakage error		$I_{In} \times R_{AS}$			mV	I_{In} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	6
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	6

1. All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{REFO}$
2. Typical values assume V_{REFO} = 3.0 V, Temp = 25 °C, f_{ADCK} = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)

6. ADC conversion clock < 3 MHz

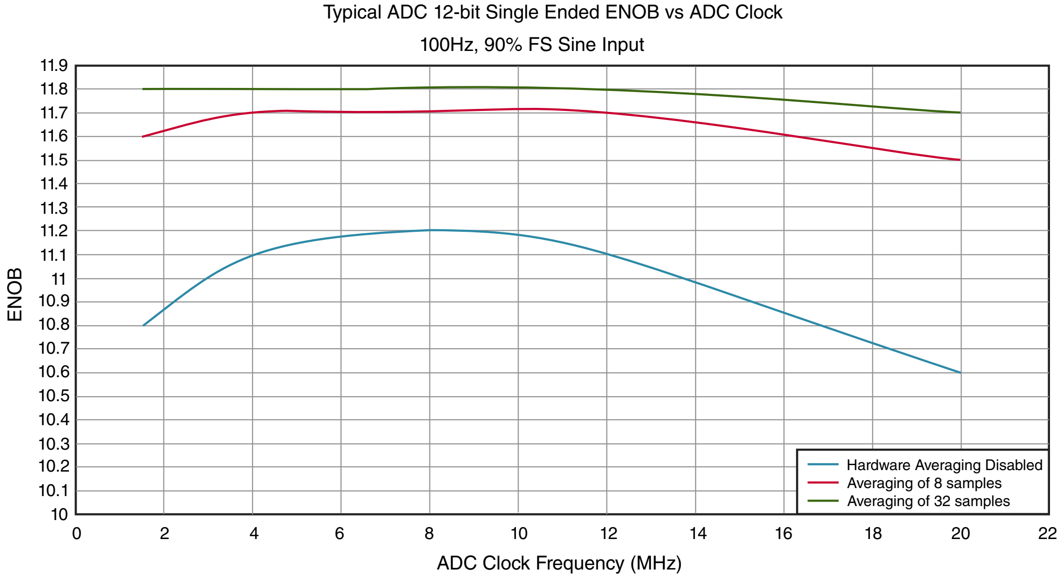


Figure 10. Typical ENOB vs. ADC_CLK for 12-bit single-ended mode

3.6.2 CMP and 6-bit DAC electrical specifications

Table 29. Comparator and 6-bit DAC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{DD}	Supply voltage	1.71	—	3.6	V
I_{DDHS}	Supply current, High-speed mode (EN=1, PMODE=1)	—	—	200	μA
I_{DDLS}	Supply current, low-speed mode (EN=1, PMODE=0)	—	—	20	μA
V_{AIN}	Analog input voltage	V_{SS} – 0.3	—	V_{DD}	V
V_{AIO}	Analog input offset voltage	—	—	20	mV
V_H	Analog comparator hysteresis[1]				
	• CR0[HYSTCTR] = 00	—	5	—	mV
	• CR0[HYSTCTR] = 01	—	10	—	mV
	• CR0[HYSTCTR] = 10	—	20	—	mV
	• CR0[HYSTCTR] = 11	—	30	—	mV
V_{CMPOh}	Output high	V_{DD} – 0.5	—	—	V
V_{CMPOl}	Output low	—	—	0.5	V
t_{DHS}	Propagation delay, high-speed mode (EN=1, PMODE=1)	20	50	200	ns
t_{DLS}	Propagation delay, low-speed mode (EN=1, PMODE=0)	80	250	600	ns

Table continues on the next page...

Table 29. Comparator and 6-bit DAC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit
	Analog comparator initialization delay[2]	—	—	40	μs
I_{DAC6b}	6-bit DAC current adder (enabled)	—	7	—	μA
INL	6-bit DAC integral non-linearity	–0.5	—	0.5	LSB[3]
DNL	6-bit DAC differential non-linearity	–0.3	—	0.3	LSB

1. Typical hysteresis is measured with input voltage range limited to 0.6 to V_{DD}–0.6 V.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]) and the comparator output settling to a stable level.
3. 1 LSB = $V_{reference}$/64

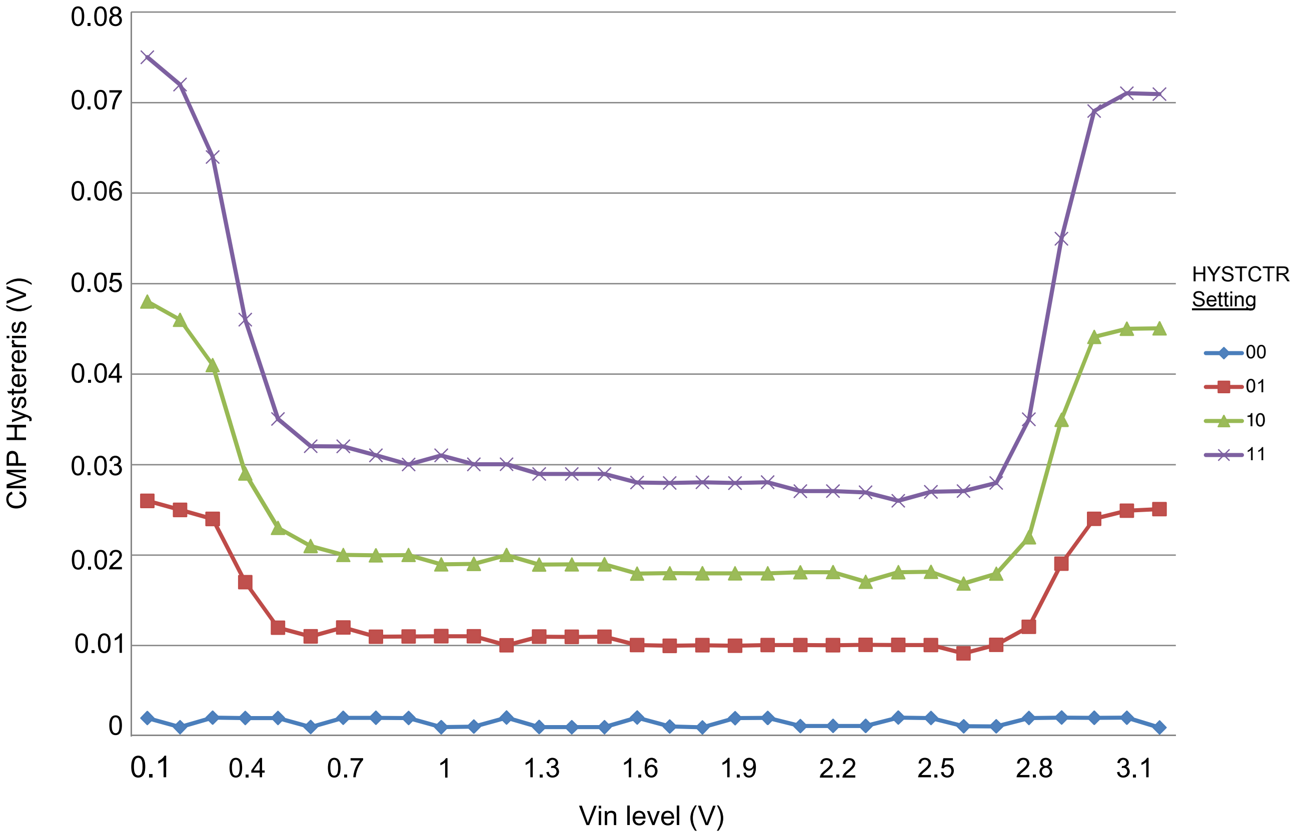


Figure 11. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)

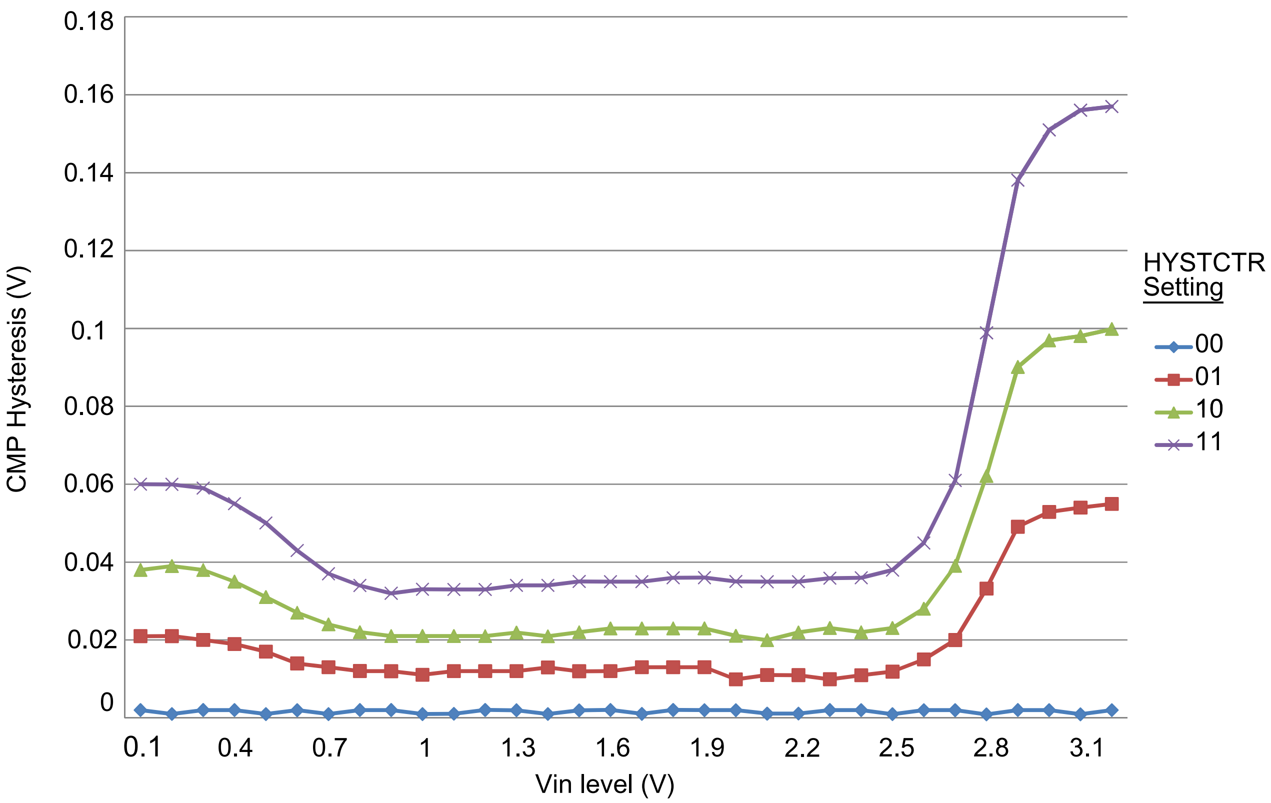


Figure 12. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)

3.6.3 Voltage reference electrical specifications

Table 30. VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	
T_A	Temperature	Operating temperature range of the device		°C	
C_L	Output load capacitance	100		nF	1, 2

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.
2. The load capacitance should not exceed +/-25% of the nominal specified C_L value over the operating temperature range of the device.

Table 31 is tested under the condition of setting VREF_TRM[CHOPEN], VREF_SC[REGEN] and VREF_SC[ICOMPEN] bits to 1.

Table 31. VREF full-range operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{out}	Voltage reference output with factory trim at nominal V_{DDA} and temperature=25C	1.1965	1.2	1.2027	V	1
V_{out}	Voltage reference output — factory trim	1.1584	—	1.2376	V	1
V_{out}	Voltage reference output — user trim	1.198	—	1.202	V	1
V_{step}	Voltage reference trim step	—	0.5	—	mV	1
V_{tdrift}	Temperature drift (Vmax -Vmin across the full temperature range: 0 to 70°C)	—	—	50	mV	1
Ac	Aging coefficient	—	—	400	uV/yr	
I_{bg}	Bandgap only current	—	—	80	µA	1
I_{lp}	Low-power buffer current	—	—	360	uA	1
I_{hp}	High-power buffer current	—	—	1	mA	1
ΔV_{LOAD}	Load regulation				µV	1, 2
	• current = ± 1.0 mA	—	200	—		
T_{stup}	Buffer startup time	—	—	100	µs	
V_{vdrift}	Voltage drift (Vmax -Vmin across the full voltage range)	—	2	—	mV	1

1. See the chip's Reference Manual for the appropriate settings of the VREF Status and Control register.
2. Load regulation voltage is the difference between the VREF_OUT voltage with no load vs. voltage with defined load

Table 32. VREF limited-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
T_A	Temperature	0	50	°C	

Table 33. VREF limited-range operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
V_{out}	Voltage reference output with factory trim	1.173	1.225	V	

3.7 Timers

See General switching specifications.

3.8 Communication interfaces

3.8.1 SPI switching specifications

The Serial Peripheral Interface (SPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The following tables provide timing characteristics for classic SPI timing modes. See the SPI chapter of the chip's Reference Manual for information about the modified transfer formats used for communicating with slower peripheral devices.

All timing is shown with respect to 20% V_{DD} and 80% V_{DD} thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all SPI pins.

Table 34. SPI master mode timing on slew rate disabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} – 30	1024 x t_{periph}	ns	—
6	t_{SU}	Data setup time (inputs)	22	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	10	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	t_{periph} – 25	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For SPI0, f_{periph} is the bus clock (f_{BUS}).
2. $t_{periph} = 1/f_{periph}$

Table 35. SPI master mode timing on slew rate enabled pads

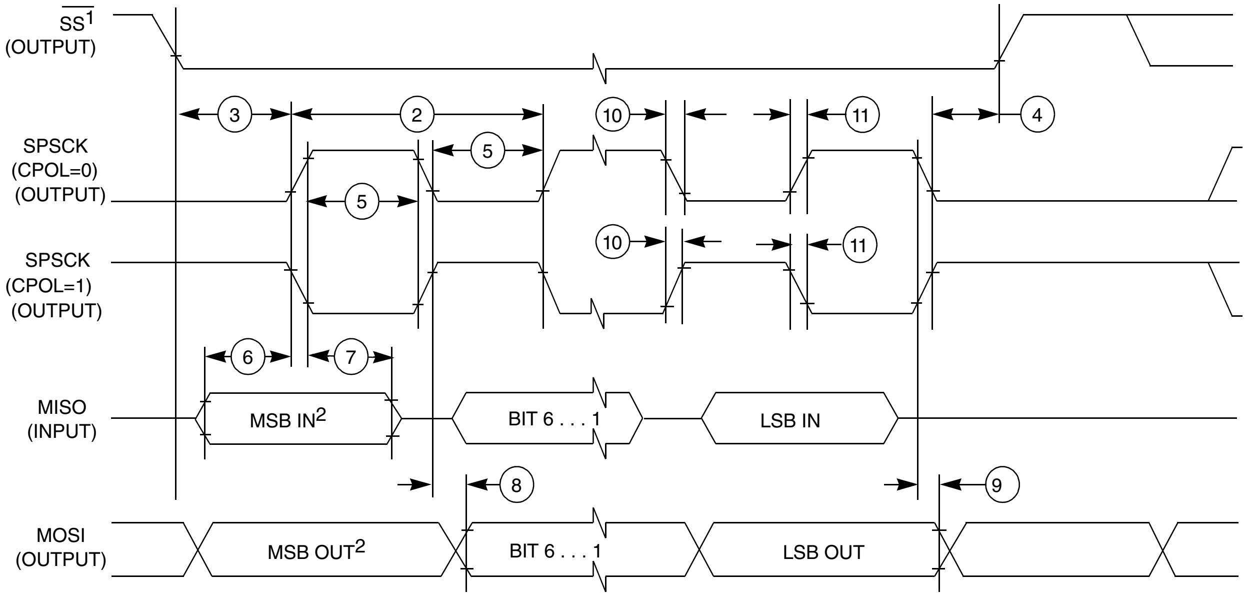
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} – 30	1024 x t_{periph}	ns	—

Table continues on the next page...

Table 35. SPI master mode timing on slew rate enabled pads (continued)

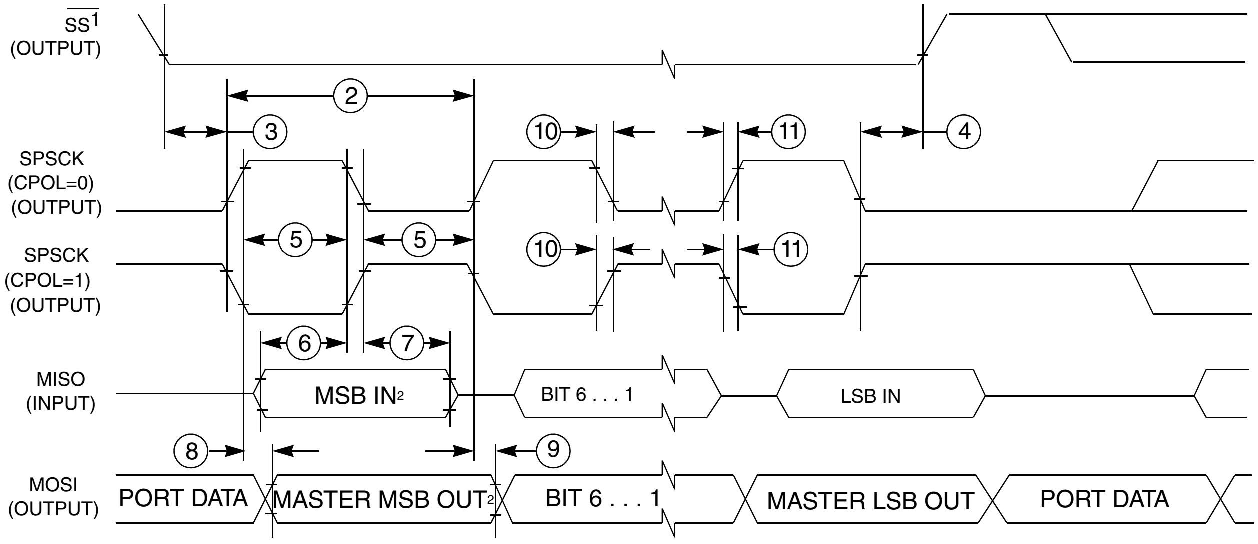
Num.	Symbol	Description	Min.	Max.	Unit	Note
6	t_{SU}	Data setup time (inputs)	96	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	52	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	t_{periph} – 25	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For SPI0, f_{periph} is the bus clock (f_{BUS}).
2. t_{periph} = 1/f_{periph}



1. If configured as an output.
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 13. SPI master mode timing (CPHA = 0)



1.If configured as output

2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 14. SPI master mode timing (CPHA = 1)

Table 36. SPI slave mode timing on slew rate disabled pads

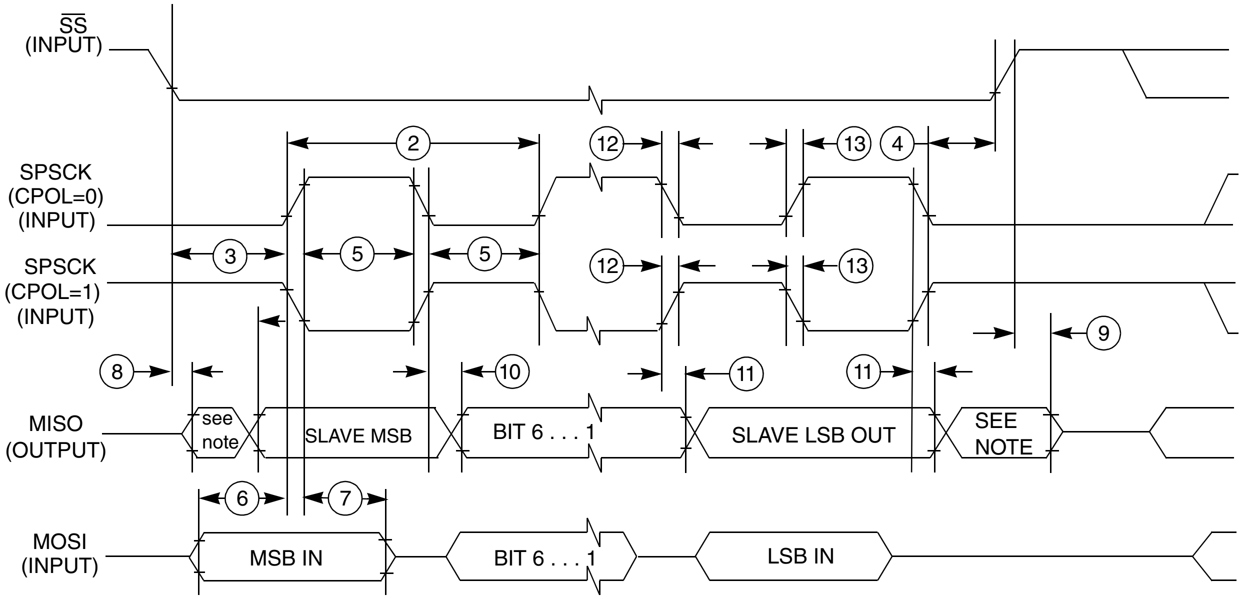
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCK}	SPSCK period	4 x t_{periph}	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{periph} - 30$	—	ns	—
6	t_{SU}	Data setup time (inputs)	3	—	ns	—
7	t_{HI}	Data hold time (inputs)	7	—	ns	—
8	t_a	Slave access time	23	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	23	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	25.7	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	$t_{periph} - 25$	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For SPI0, f_{periph} is the bus clock (f_{BUS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

Table 37. SPI slave mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCK}	SPSCK period	4 x t_{periph}	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{periph} – 30$	—	ns	—
6	t_{SU}	Data setup time (inputs)	2	—	ns	—
7	t_{HI}	Data hold time (inputs)	7	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	122	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	$t_{periph} – 25$	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For SPI0, f_{periph} is the bus clock (f_{BUS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state



NOTE: Not defined

Figure 15. SPI slave mode timing (CPHA = 0)

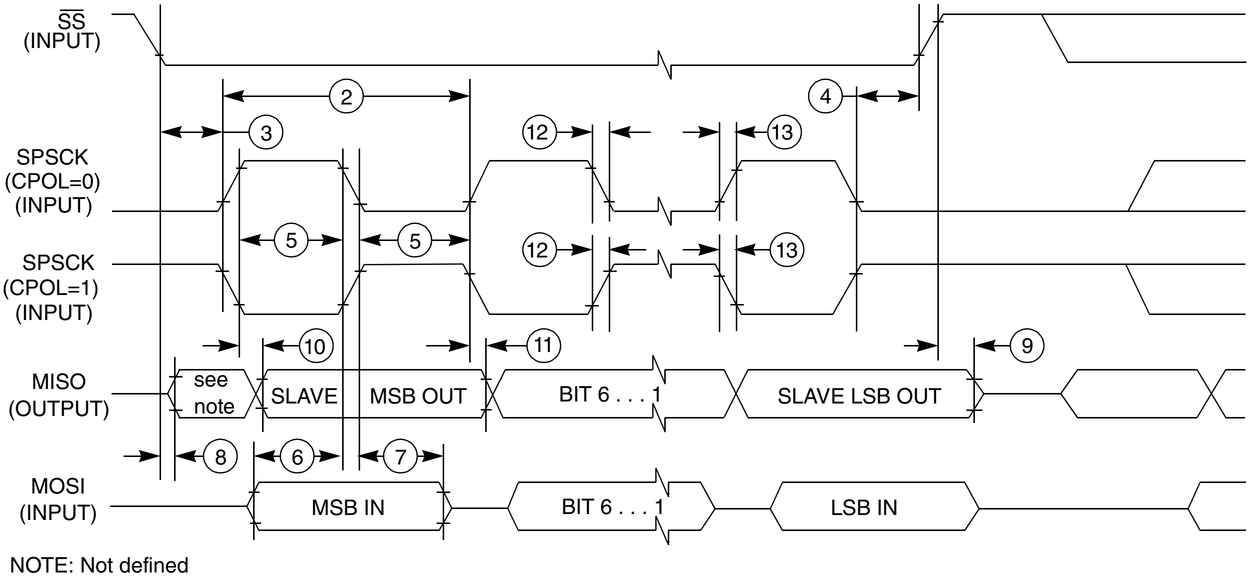


Figure 16. SPI slave mode timing (CPHA = 1)

3.8.2 Inter-Integrated Circuit Interface (I2C) timing

Table 38. I2C timing

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Minimum	Maximum	Minimum	Maximum	
SCL Clock Frequency	f_{SCL}	0	100[1]	0	400[2]	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	4	—	0.6	—	µs
LOW period of the SCL clock	t_{LOW}	4.7	—	1.25	—	µs
HIGH period of the SCL clock	t_{HIGH}	4	—	0.6	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	4.7	—	0.6	—	µs
Data hold time for I^2C bus devices	t_{HD}; DAT	0[3]	3.45[4]	0[5]	0.9[3]	µs
Data set-up time	t_{SU}; DAT	250[6]	—	100[4, 7]	—	ns
Rise time of SDA and SCL signals	t_r	—	1000	20 +0.1C_b[8]	300	ns
Fall time of SDA and SCL signals	t_f	—	300	20 +0.1C_b[7]	300	ns
Set-up time for STOP condition	t_{SU}; STO	4	—	0.6	—	µs
Bus free time between STOP and START condition	t_{BUF}	4.7	—	1.3	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	N/A	N/A	0	50	ns

1. The PTB3 and PTB4 pins can support only the Standard mode.
2. The maximum SCL Clock Frequency in Fast mode with maximum bus loading can be achieved only when using the high drive pins across the full voltage range and when using the normal drive pins and VDD ≥ 2.7 V.

3. The master mode I^2C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no slaves acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
4. The maximum tHD; DAT must be met only if the device does not stretch the LOW period (tLOW) of the SCL signal.
5. Input signal Slew = 10 ns and Output Load = 50 pF
6. Set-up time in slave-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.
7. A Fast mode I^2C bus device can be used in a Standard mode I2C bus system, but the requirement $t_{SU;\ DAT} \geq 250$ ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{rmax} + t_{SU;\ DAT} = 1000 + 250 = 1250$ ns (according to the Standard mode I^2C bus specification) before the SCL line is released.
8. C_b = total capacitance of the one bus line in pF.

To achieve 1MHz I2C clock rates, consider the following recommendations:

- To counter the effects of clock stretching, the I2C baud Rate select bits can be configured for faster than desired baud rate.
- Use high drive pad and DSE bit should be set in PORTx_PCRn register.
- Minimize loading on the I2C SDA and SCL pins to ensure fastest rise times for the SCL line to avoid clock stretching.
- Use smaller pull up resistors on SDA and SCL to reduce the RC time constant.

Table 39. I^2C 1Mbit/s timing

Characteristic	Symbol	Minimum	Maximum	Unit
SCL Clock Frequency	f_{SCL}	0	1[1, 2]	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	0.26	—	µs
LOW period of the SCL clock	t_{LOW}	0.5	—	µs
HIGH period of the SCL clock	t_{HIGH}	0.26	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	0.26	—	µs
Data hold time for I_2C bus devices	t_{HD}; DAT	0	—	µs
Data set-up time	t_{SU}; DAT	50	—	ns
Rise time of SDA and SCL signals	t_r	$20 + 0.1C_b$	120	ns
Fall time of SDA and SCL signals	t_f	$20 + 0.1C_b$[3]	120	ns
Set-up time for STOP condition	t_{SU}; STO	0.26	—	µs
Bus free time between STOP and START condition	t_{BUF}	0.5	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

1. The maximum SCL clock frequency of 1 Mbit/s can support 200 pF bus loading when using the normal drive pins and VDD ≥ 2.7 V.
2. The maximum SCL clock frequency of 1 Mbit/s can support maximum bus loading when using the high drive pins across the full voltage range.
3. C_b = total capacitance of the one bus line in pF.

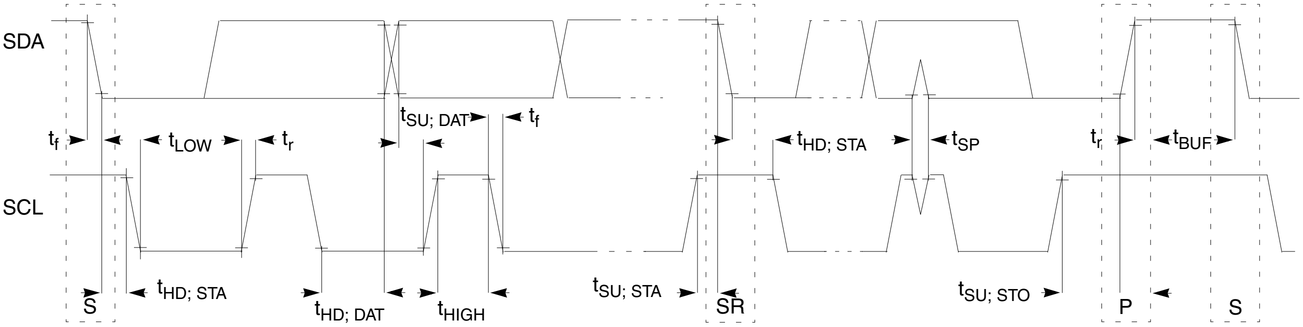


Figure 17. Timing definition for devices on the I^{2}C bus

3.8.3 UART

See General switching specifications.

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to **nxp.com** and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
16-pin QFN	98ASA00525D
24-pin QFN	98ASA00602D

5 Pinout

5.1 MCX C041 signal multiplexing and pin assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

NOTE

PTB3 and PTB4 are true open drain pins. The external pullup resistor must be added to make them output correct values in using I2C, GPIO, and LPUART0.

24 QFN	16 QFN	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5
1	—	PTB6/ IRQ_2/ LPTMR0_ALT3	DISABLED		PTB6/ IRQ_2/ LPTMR0_ALT3	TPM1_CH1	TPM_CLKIN1		
2	—	PTB7/ IRQ_3	DISABLED		PTB7/ IRQ_3	TPM1_CH0			
3	1	VDD	VDD	VDD					
4	2	VSS	VSS	VSS					
5	3	PTA3	EXTAL0	EXTAL0	PTA3	I2C0_SCL	I2C0_SDA	LPUART0_TX	
6	4	PTA4	XTAL0	XTAL0	PTA4	I2C0_SDA	I2C0_SCL	LPUART0_RX	CLKOUT
7	5	PTA5/ RTC_CLK_IN	DISABLED		PTA5/ RTC_CLK_IN	TPM0_CH1	SPI0_SS_b		
8	6	PTA6	DISABLED		PTA6	TPM0_CH0	SPI0_MISO		
9	—	PTB10	DISABLED		PTB10	TPM0_CH1	SPI0_SS_b		
10	—	PTB11	DISABLED		PTB11	TPM0_CH0	SPI0_MISO		
11	7	PTA7/ IRQ_4	DISABLED		PTA7/ IRQ_4	SPI0_MISO	SPI0_MOSI		
12	8	PTB0/ IRQ_5/ LLWU_P4	ADC0_SE9	ADC0_SE9	PTB0/ IRQ_5/ LLWU_P4	EXTRG_IN	SPI0_SCK	I2C0_SCL	
13	9	PTB1/ IRQ_6	ADC0_SE8/ CMP0_IN3	ADC0_SE8/ CMP0_IN3	PTB1/ IRQ_6	LPUART0_TX	LPUART0_RX	I2C0_SDA	
14	10	PTB2/ IRQ_7	VREF_OUT/ CMP0_IN5	VREF_OUT/ CMP0_IN5	PTB2/ IRQ_7	LPUART0_RX	LPUART0_TX		
15	—	PTA8	ADC0_SE3	ADC0_SE3	PTA8	I2C0_SCL	SPI0_MOSI		
16	—	PTA9	ADC0_SE2	ADC0_SE2	PTA9	I2C0_SDA	SPI0_SCK		
17	11	PTB3/ IRQ_10	DISABLED		PTB3/ IRQ_10	I2C0_SCL	LPUART0_TX		
18	12	PTB4/ IRQ_11	DISABLED		PTB4/ IRQ_11	I2C0_SDA	LPUART0_RX		
19	13	PTB5/ IRQ_12	NMI_b	ADC0_SE1/ CMP0_IN1	PTB5/ IRQ_12	TPM1_CH1	NMI_b		
20	—	PTA12/ IRQ_13/ LPTMR0_ALT2	ADC0_SE0/ CMP0_IN0	ADC0_SE0/ CMP0_IN0	PTA12/ IRQ_13/ LPTMR0_ALT2	TPM1_CH0	TPM_CLKIN0		CLKOUT
21	—	PTB13/ CLKOUT32K	DISABLED		PTB13/ CLKOUT32K	TPM1_CH1	RTC_CLKOUT		
22	14	PTA0/ IRQ_0/ LLWU_P7	SWD_CLK	ADC0_SE15/ CMP0_IN2	PTA0/ IRQ_0/ LLWU_P7	TPM1_CH0	SWD_CLK		

24 QFN	16 QFN	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5
23	15	PTA1/ IRQ_1/ LPTMR0_ALT1	RESET_b		PTA1/ IRQ_1/ LPTMR0_ALT1	TPM_CLKIN0	RESET_b		
24	16	PTA2	SWD_DIO		PTA2	CMP0_OUT	SWD_DIO		

5.2 MCX C041 pinouts

The following figures show the pinout diagrams for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see MCX C041 signal multiplexing and pin assignments.

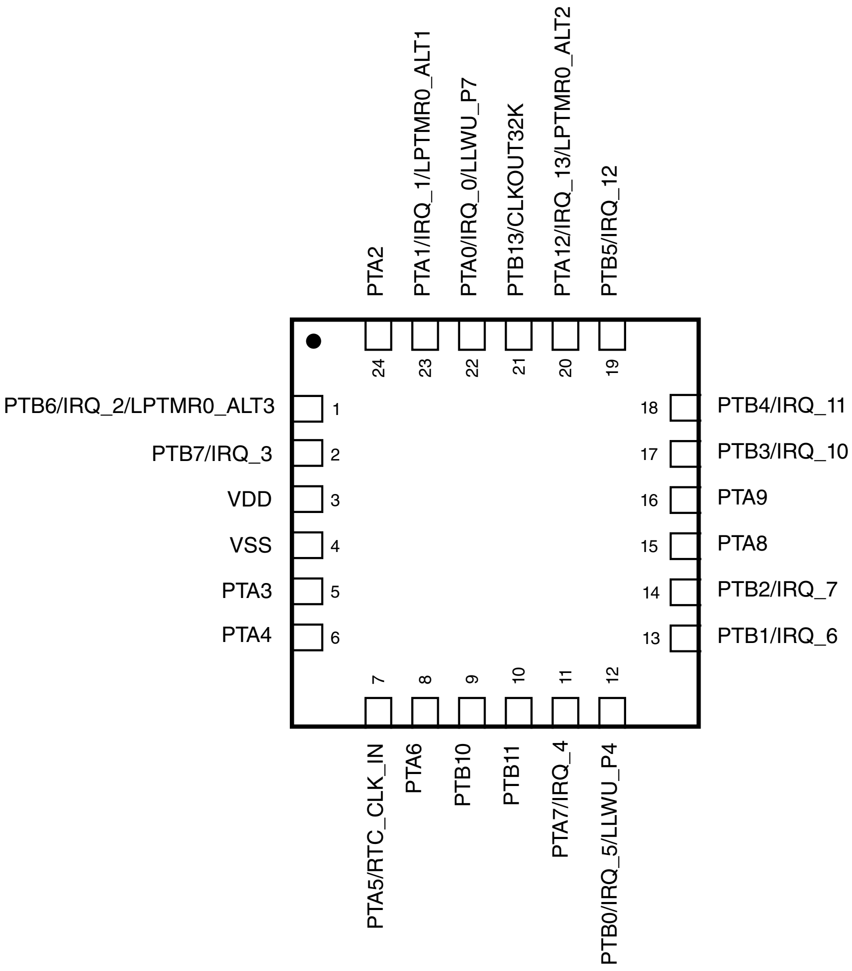


Figure 18. MCX C041 24-pin QFN pinout diagram

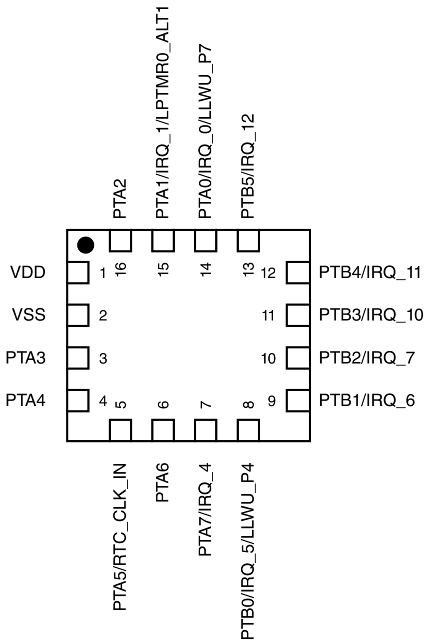


Figure 19. MCX C041 16-pin QFN pinout diagram

6 Ordering parts

6.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to **nxp.com** and perform a part number search.

7 Part identification

7.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

7.2 Format

Part numbers for this device have the following format:

B PS F C FS T PG SR PT

7.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Table 40. Part number fields description

Field	Description	Values
B	Brand	• MCX
PS	Product series name	• C
F	Family	• 0 = Entry • 1 = Baseline • 2 = Baseline Enhance • 3 = Reserved • 4 = HMI
C	Core Features	• 4 = 48 MHz
FS	Flash Size	• 1 = 32 KB • 2 = 64 KB • 3 = 128 KB • 4 = 256 KB
T	Junction Temperature range (°C)	• V = –40 to 125
PG	Package	• FG = 16 QFN (3 mm x 3 mm) • FK = 24 QFN (4 mm x 4 mm) • FM = 32QFN: 5x5x0.9 mm • FT = 48QFN: 7x7x0.9 mm • LH = 64LQFP: 10x10x1.6mm • MP = 64MAPBGA: 5x5x1.23mm
SR	Silicon Revision	• A = Initial Mask set • B = 1st Major spin
PT	Package Type	• R = Tape and Reel • T = Tray

7.4 Example

This is an example part number:

MCXC041VFK

8 Terminology and guidelines

8.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

8.1.1 Example

This is an example of an operating requirement:

Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	0.9	1.1	V

8.2 Definition: Operating behavior

Unless otherwise specified, an *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

8.2.1 Example

This is an example of an operating behavior:

Symbol	Description	Min.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	130	µA

8.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

8.3.1 Example

This is an example of an attribute:

Symbol	Description	Min.	Max.	Unit
CIN_D	Input capacitance: digital pins	—	7	pF

8.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

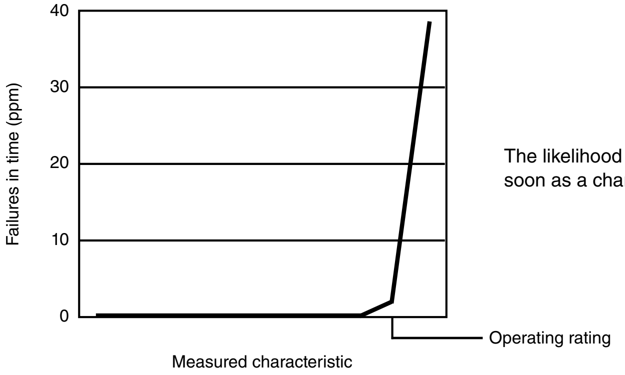
- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

8.4.1 Example

This is an example of an operating rating:

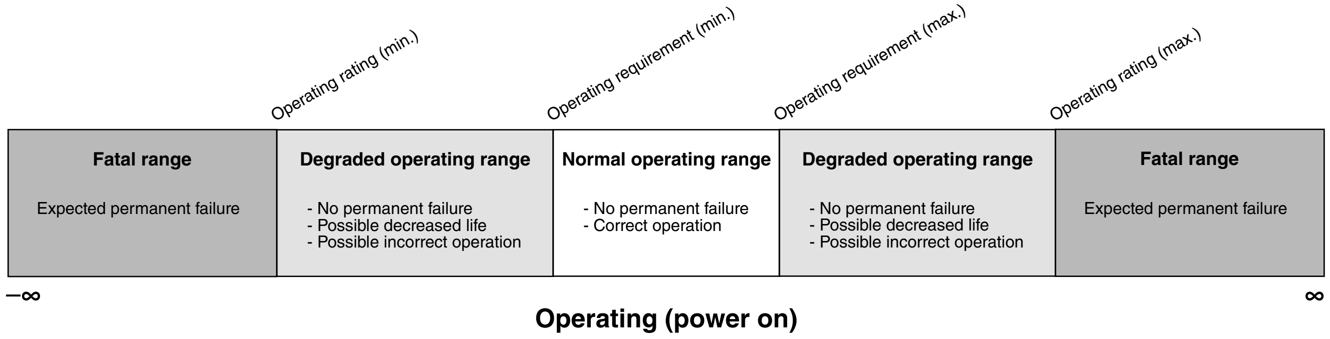
Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	–0.3	1.2	V

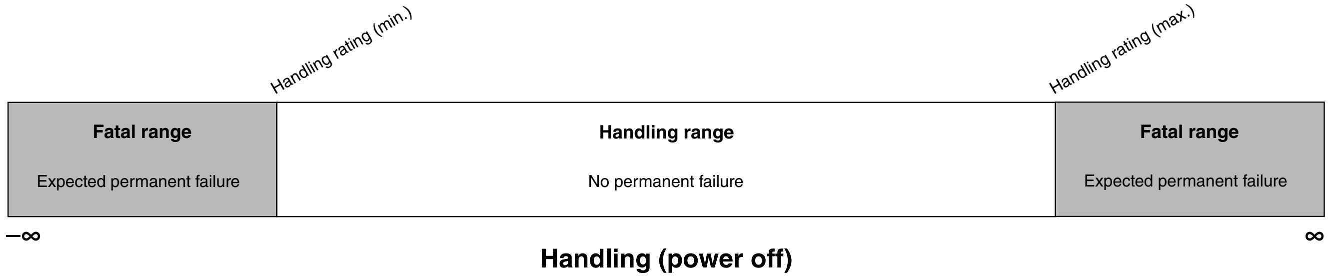
8.5 Result of exceeding a rating



The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings.

8.6 Relationship between ratings and operating requirements





8.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.

- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

8.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

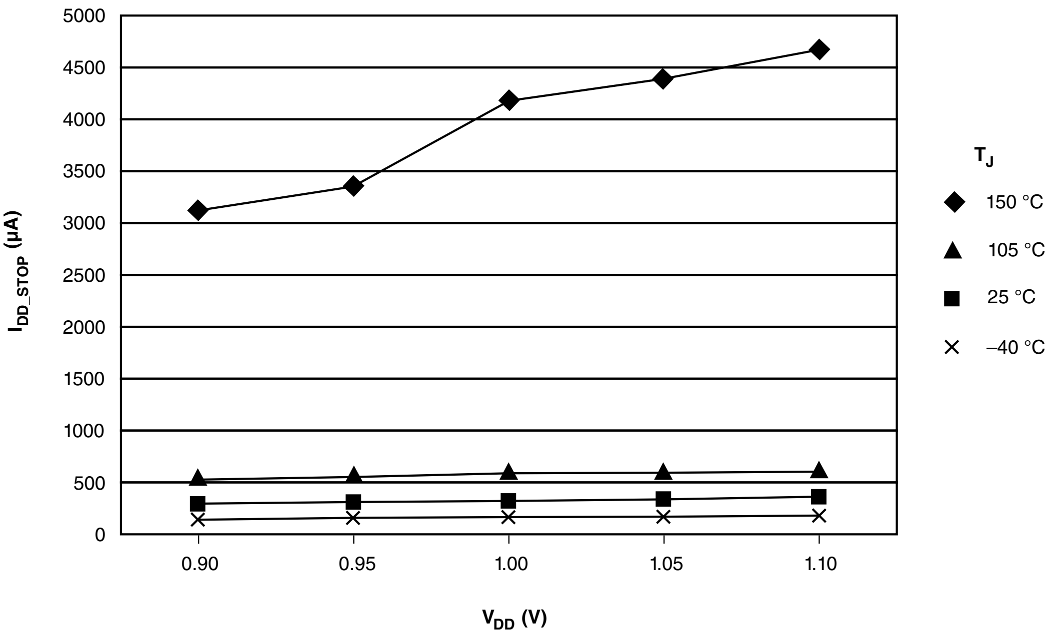
8.8.1 Example 1

This is an example of an operating behavior that includes a typical value:

Symbol	Description	Min.	Typ.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	70	130	µA

8.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:



8.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Table 41. Typical value conditions

Symbol	Description	Value	Unit
T_A	Ambient temperature	25	°C
V_{DD}	3.3 V supply voltage	3.3	V

9 Revision history

The following table provides a revision history for this document.

Table 42. Revision history

Rev. No.	Date	Substantial Changes
3.0	05/2025	• Added a row and footnote to the Voltage and current operating behaviors • Replace -40 for die junction temperature with " - "and add -40 in row for Ambient temperature in Thermal operating requirements
2.0	07/2024	Initial release.

Legal information

Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL https://www.nxp.com.

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